

A

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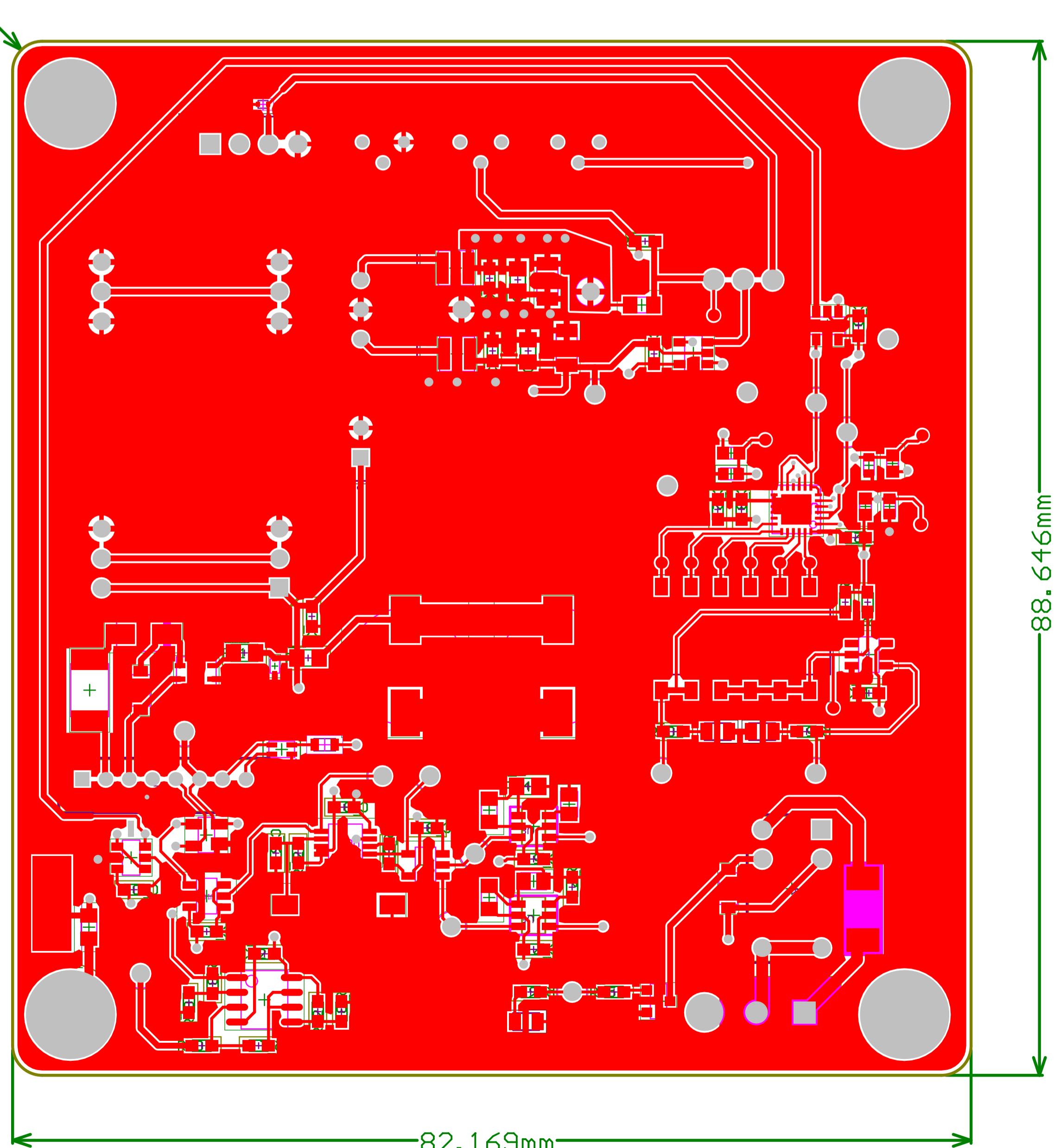
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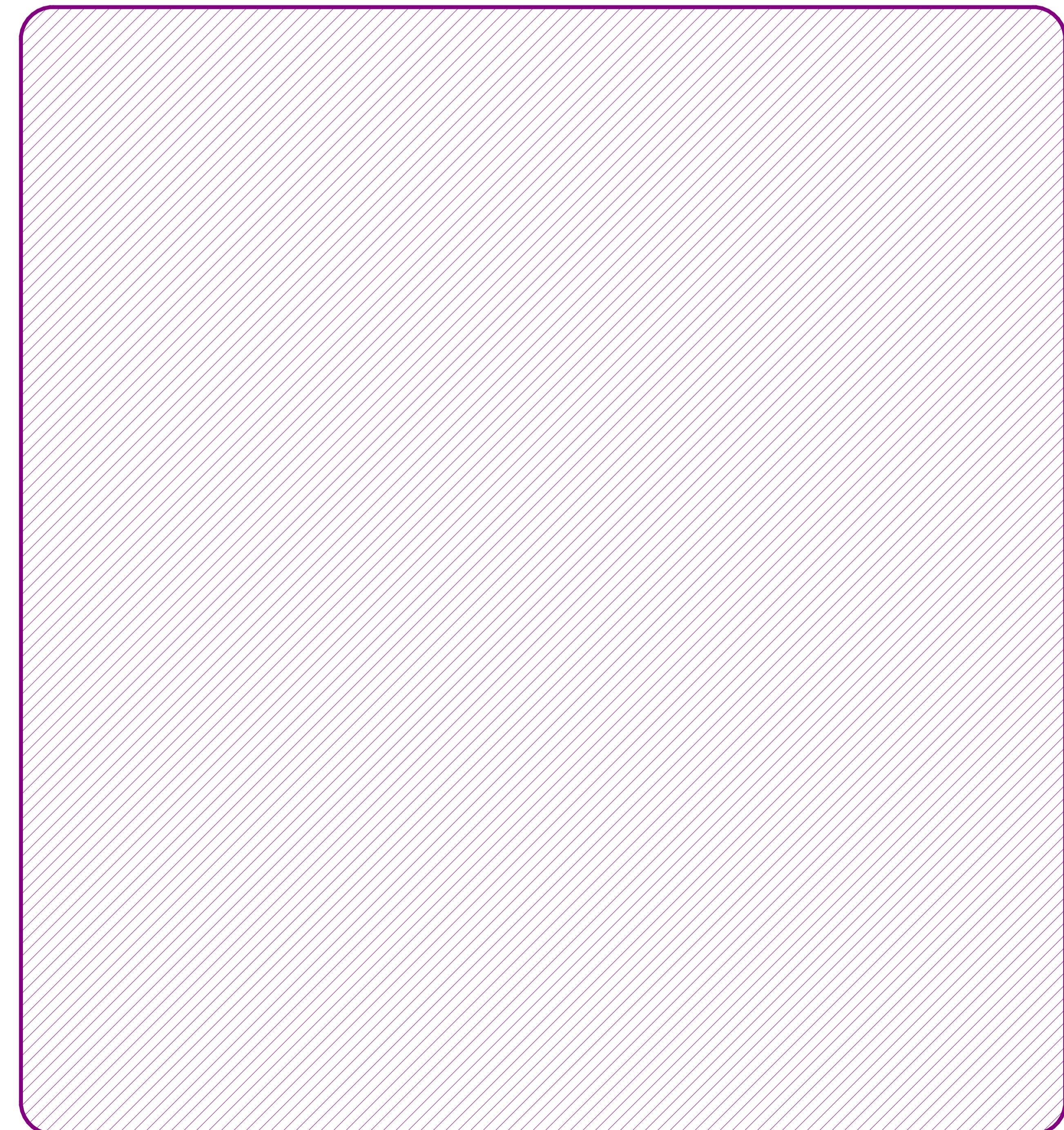
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D



Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
1	Top Layer	Copper	1.40mil		GTL	
	Dielectric 1	FR-4	58.00mil	4.2		
2	Bottom Layer	Copper	1.40mil		GBL	
	Bottom Solder	SM-001	1.00mil	4	GBS	
	Bottom Overlay				GBO	

Total board thickness: 62.80mil



Title BSPD

Size: Letter

Number:

Revision:

Date: 2/5/2020 Time: 2:26:28 PM Sheet 1 of 1

File: UVM AERO BSPD.PcbDoc

Designer:  
Andrew Katz  
aakatz@gmail.com  
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AERO

A

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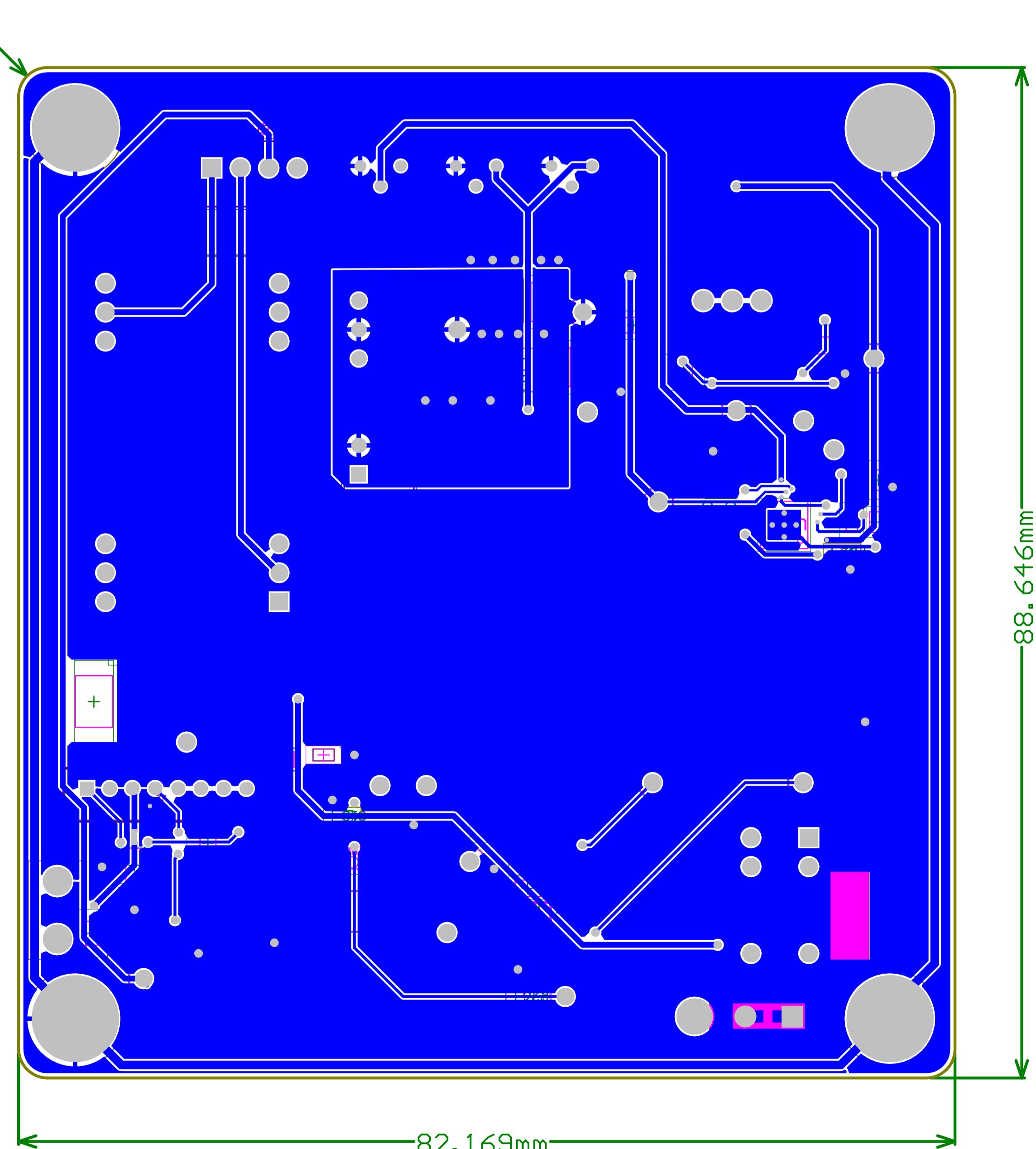
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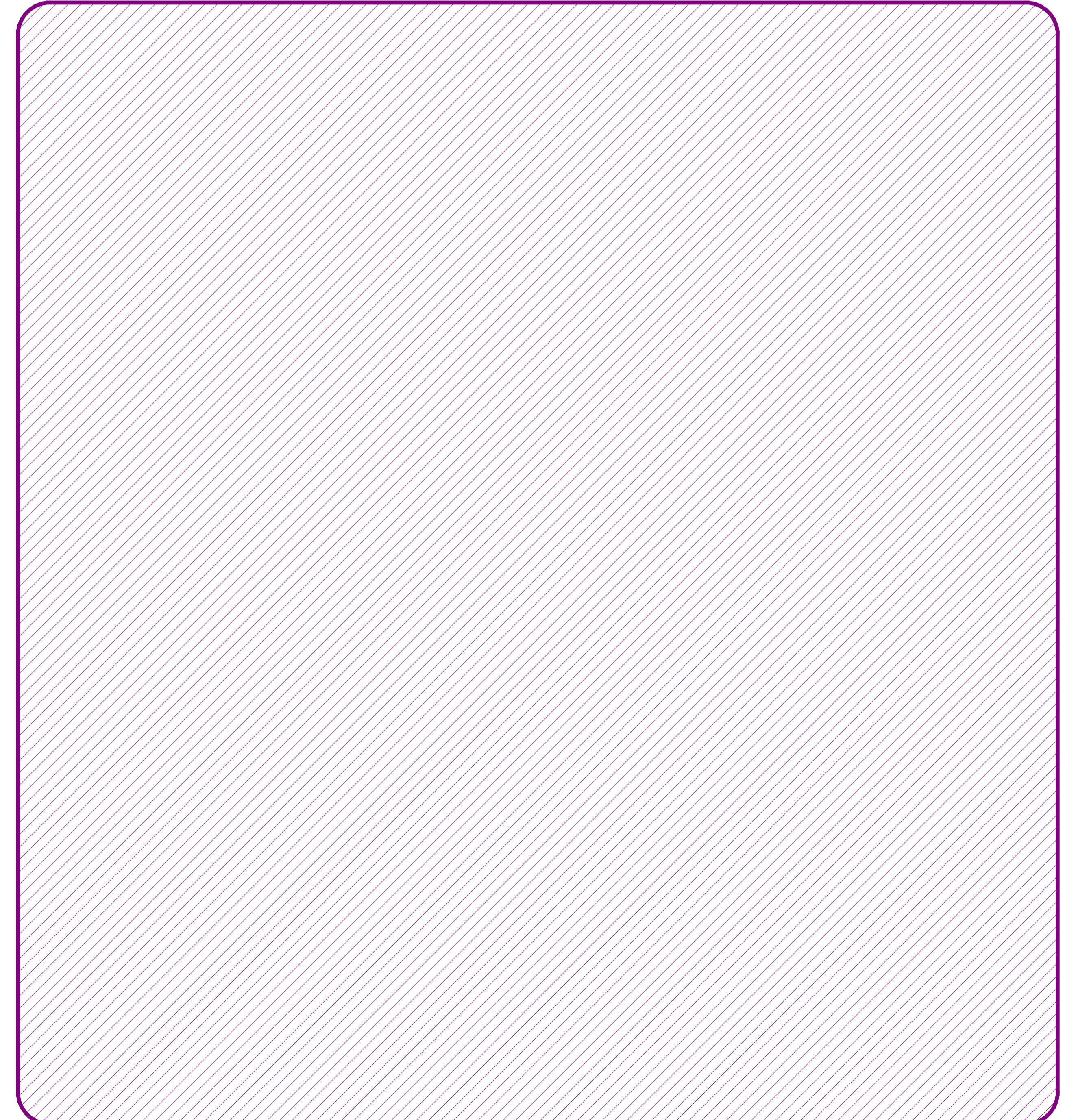
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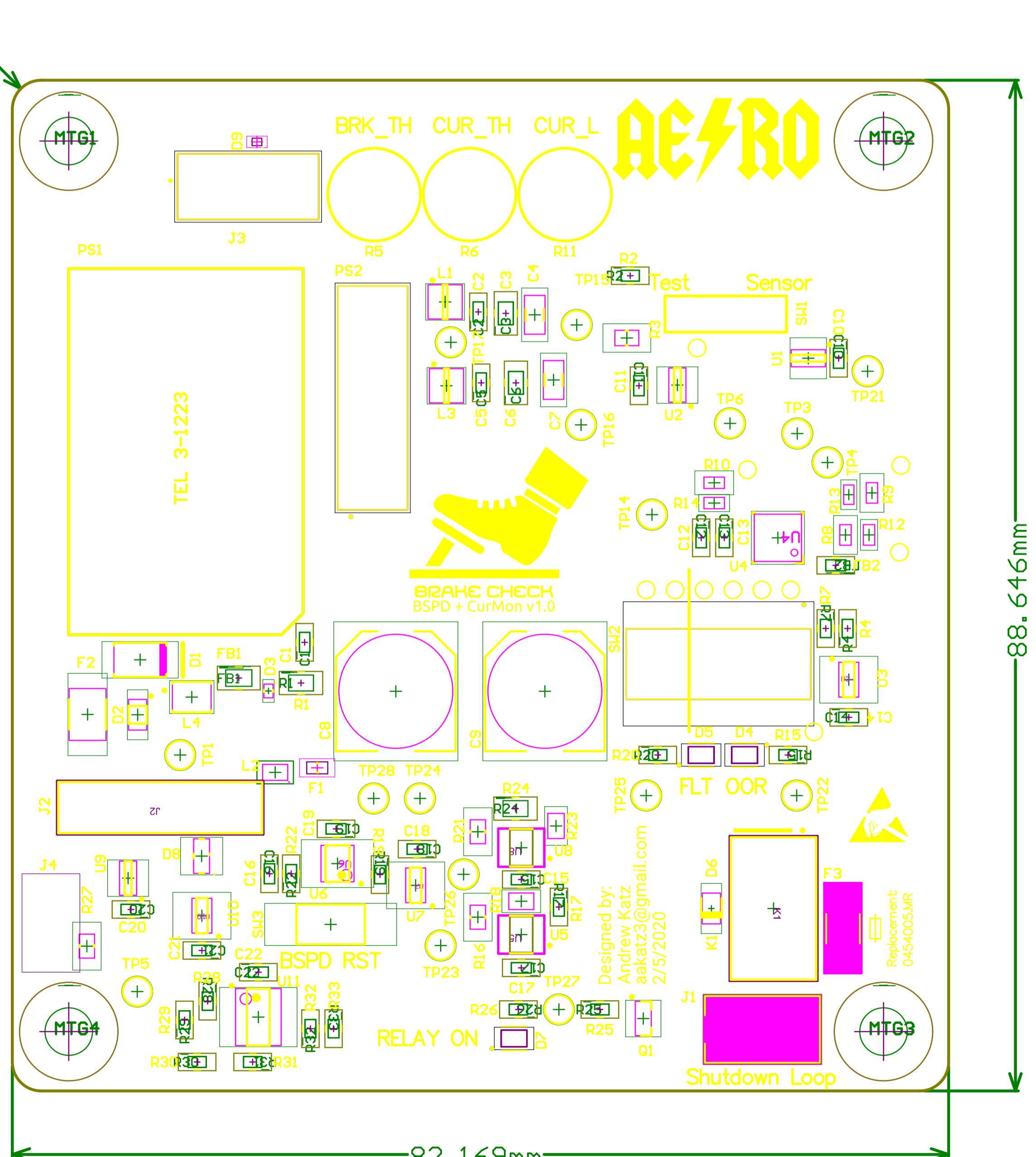
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	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
1	Top Layer	Copper	1.40mil		GTL	
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	Bottom Solder	SM-001	1.00mil	4	GBS	
	Bottom Overlay				GBO	

Total board thickness: 62.80mil



Title <b>BSPD</b>			Designer: Andrew Katz aakatz@gmail.com
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Date: 2/5/2020	Time: 2:26:28 PM	Sheet 1 of 1	*
File: UVM AERO BSPD.PcbDoc			

**AERO**



Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
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	Bottom Solder	SM-001	1.00mil	4	GBS	
	Bottom Overlay				GBO	



Title <b>BSPD</b>			Designer: Andrew Katz aakatz3@gmail.com
Size: Letter	Number:	Revision:	*
Date: 2/5/2020	Time: 2:26:28 PM	Sheet 1 of 1	*
File: UVM AERO BSPD.PcbDoc			

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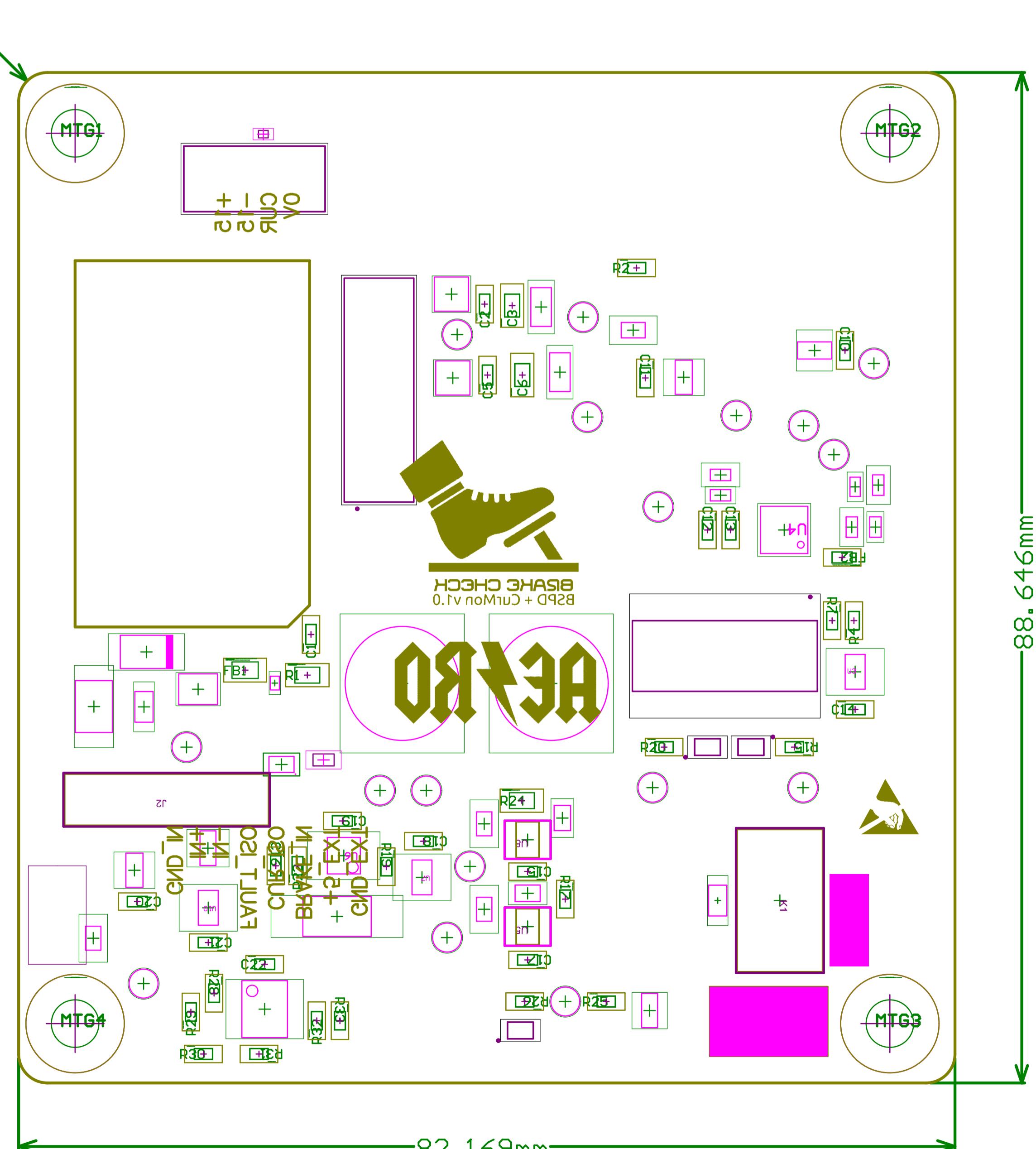
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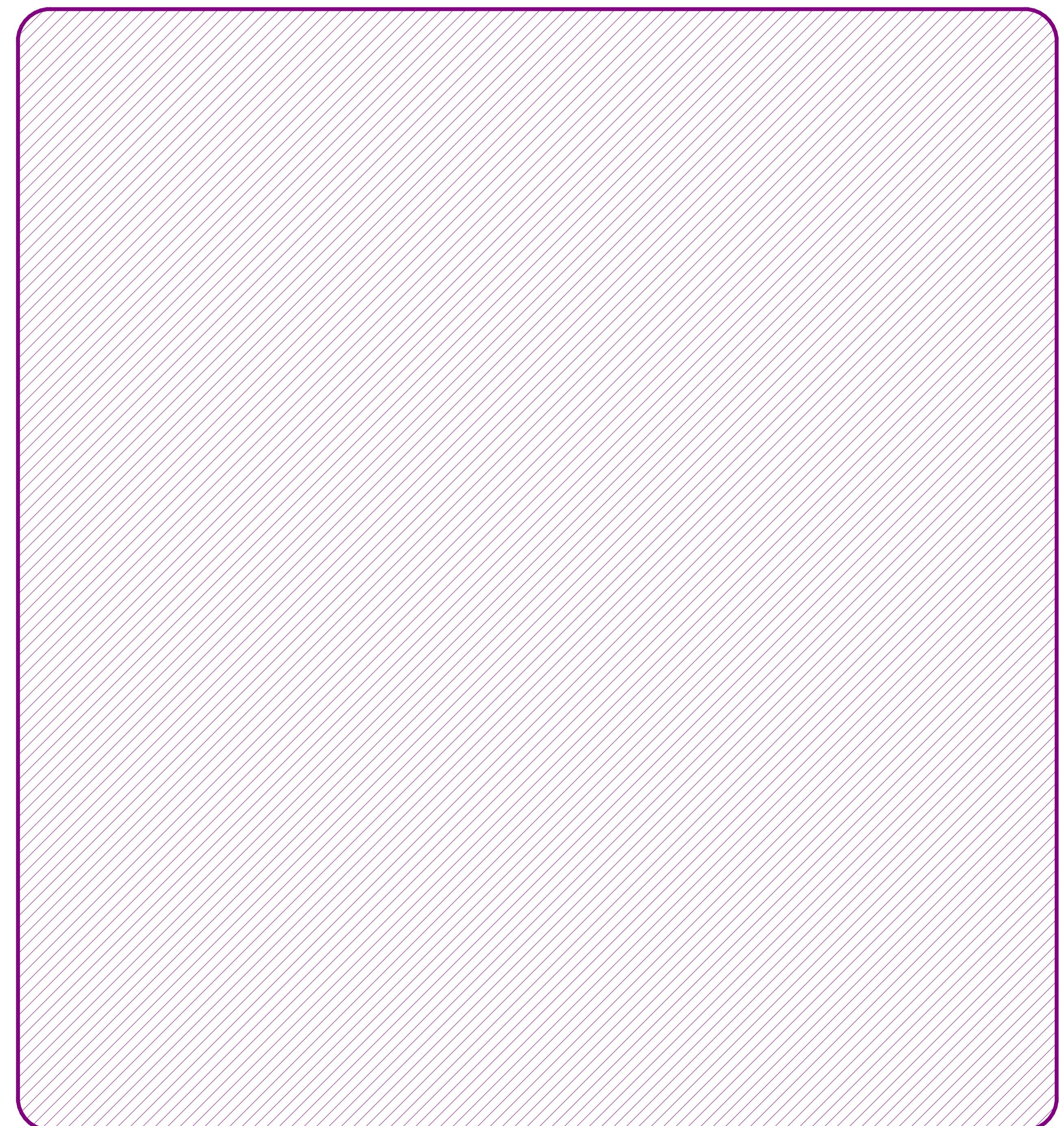
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Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
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A

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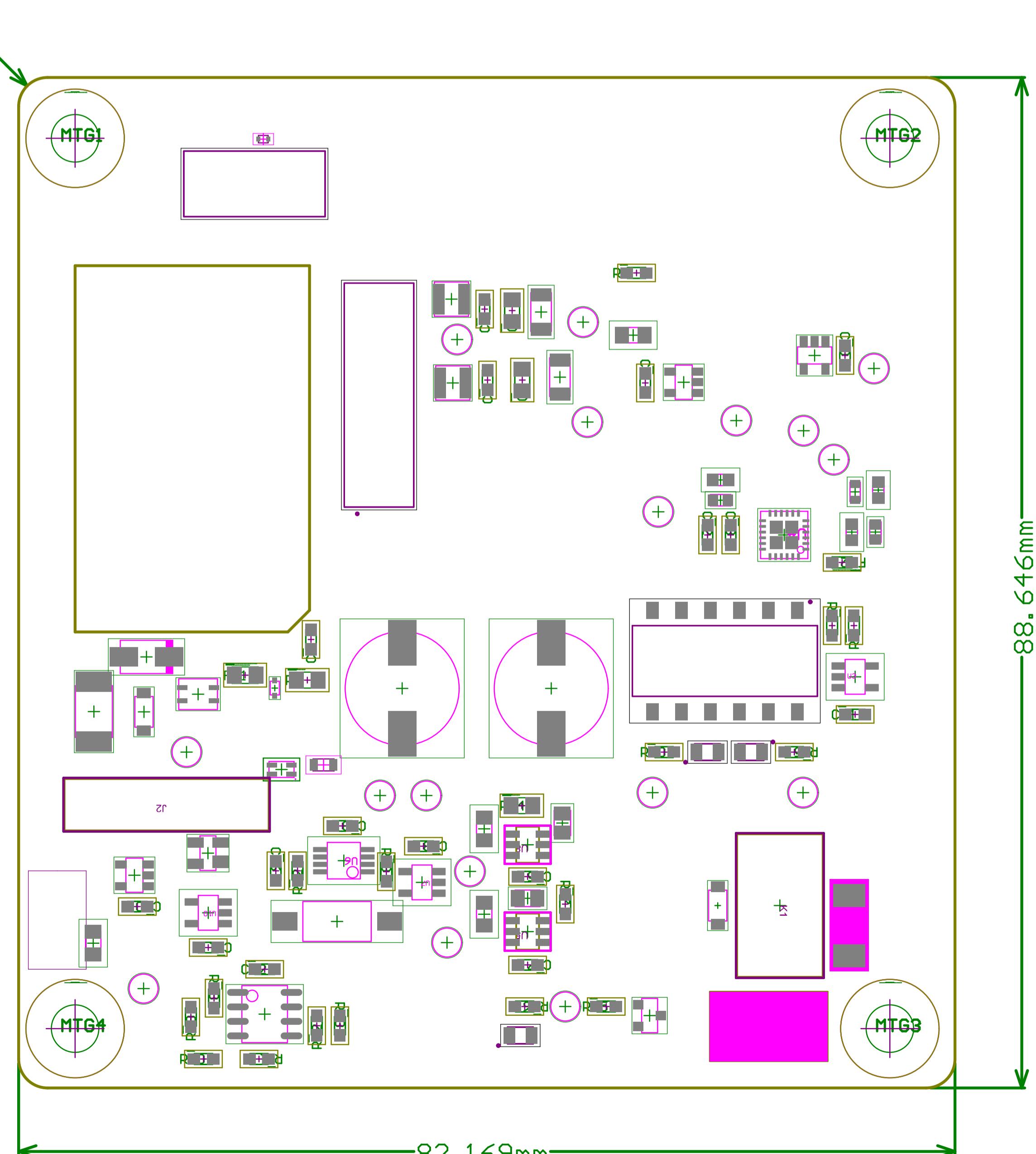
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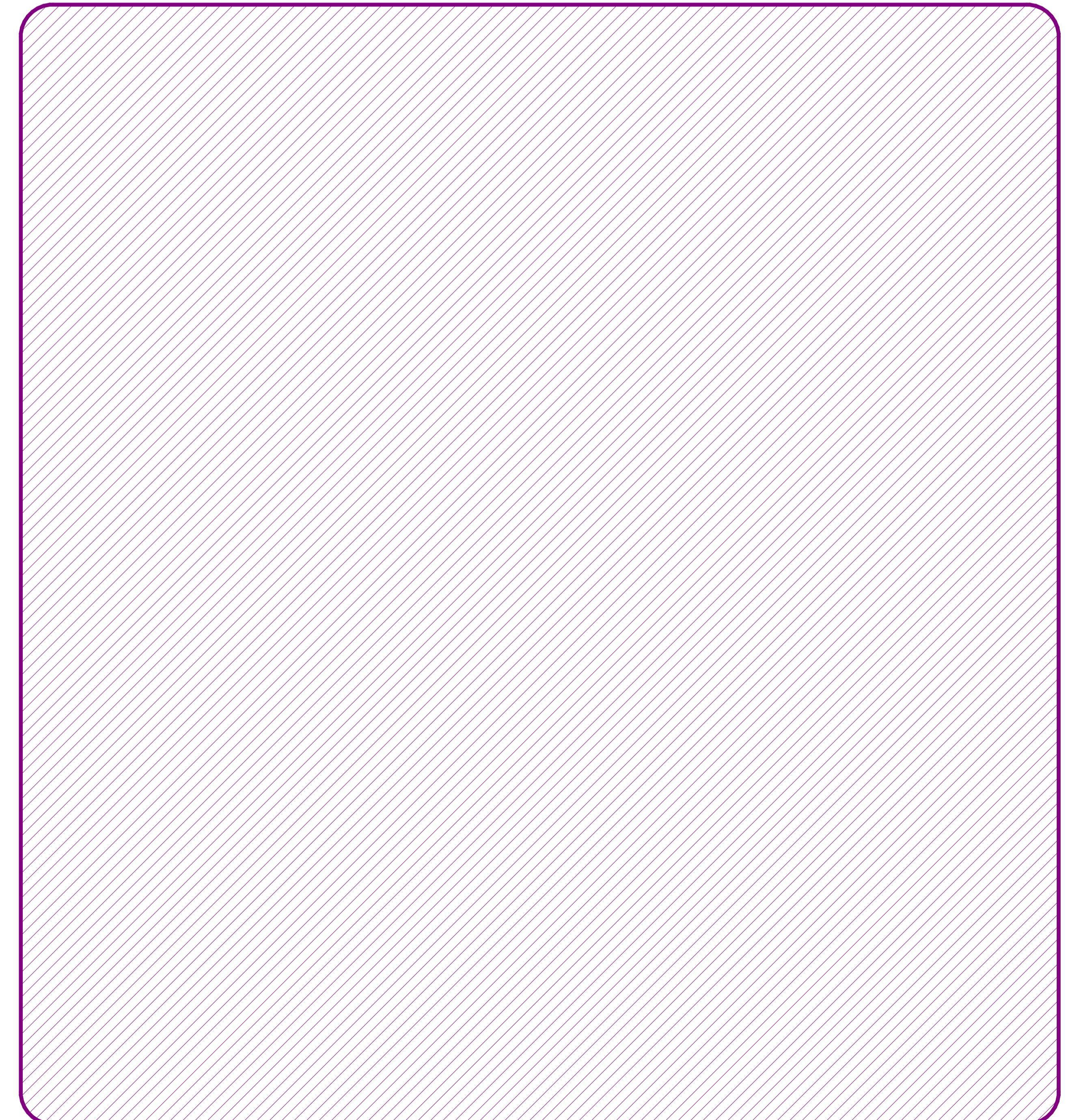
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	Top Overlay				GTO	
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aakatz@gmail.com  
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AE<sup>2</sup>RO

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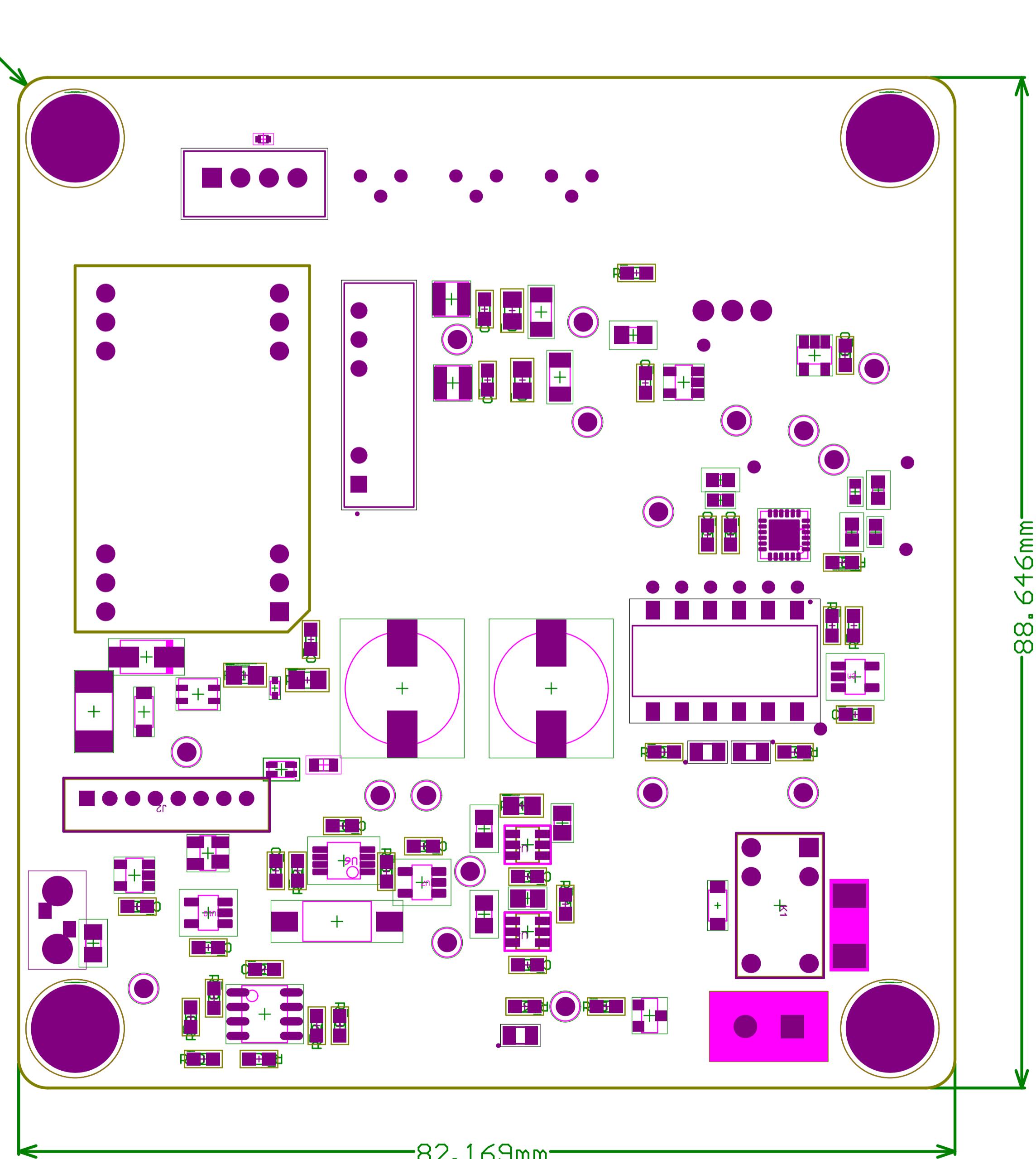
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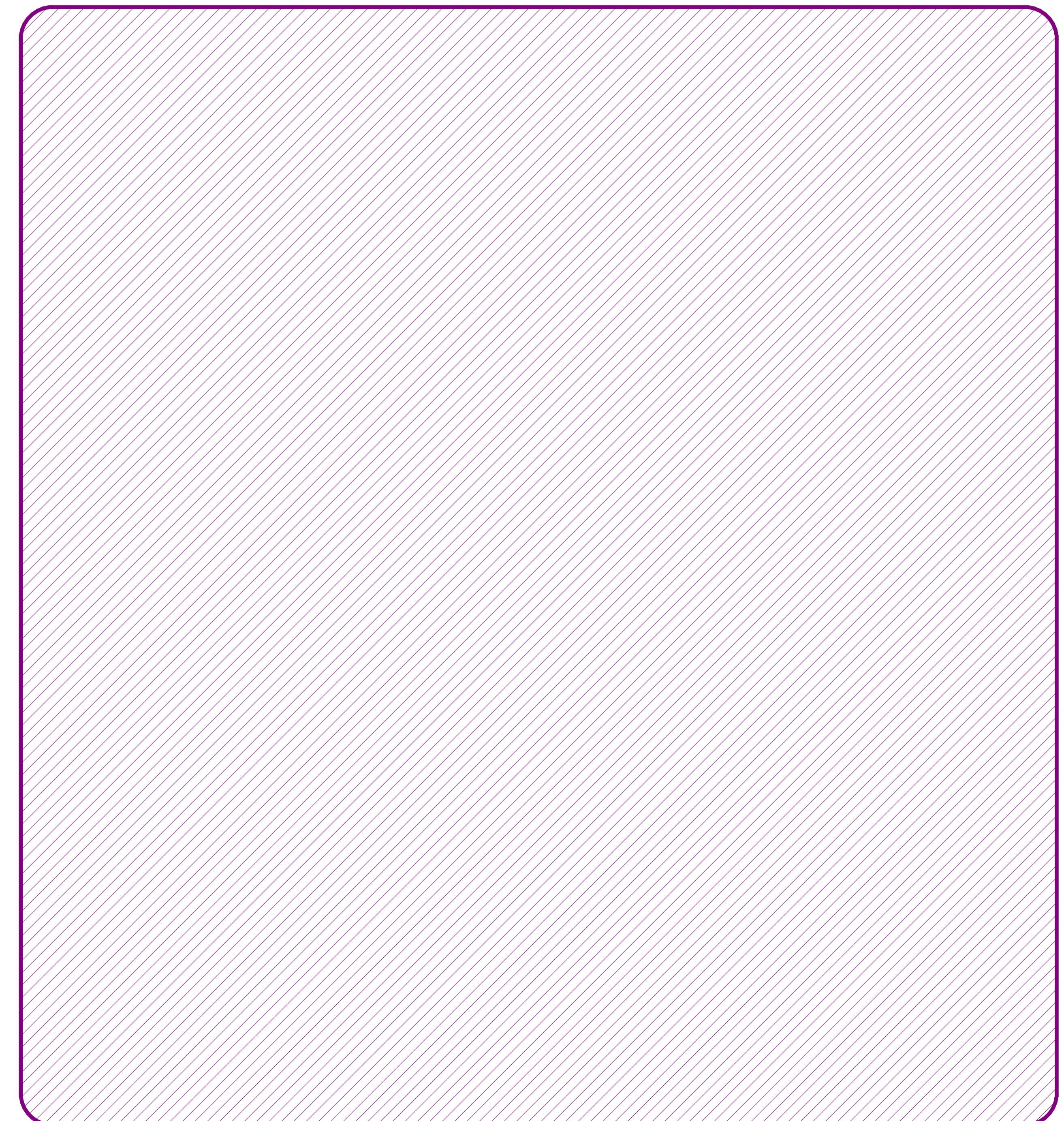
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	Top Solder	SM-001	1.00mil	4	GTS	
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	Bottom Overlay				GBO	

Total board thickness: 62.80mil



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Time: 2:26:28 PM	Sheet 1 of 1
File: UVM AERO BSPD.PcbDoc	*

**AERO**

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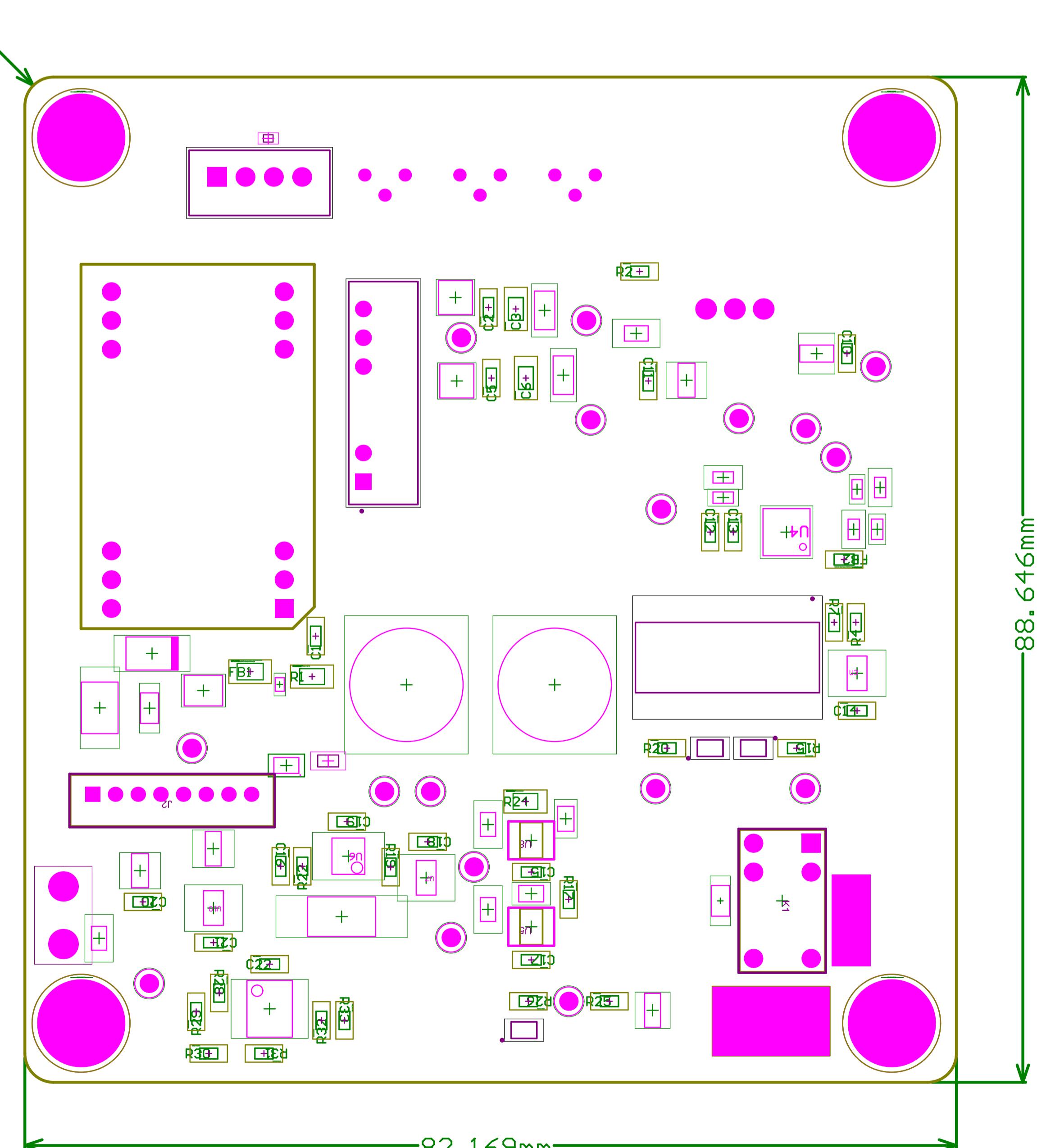
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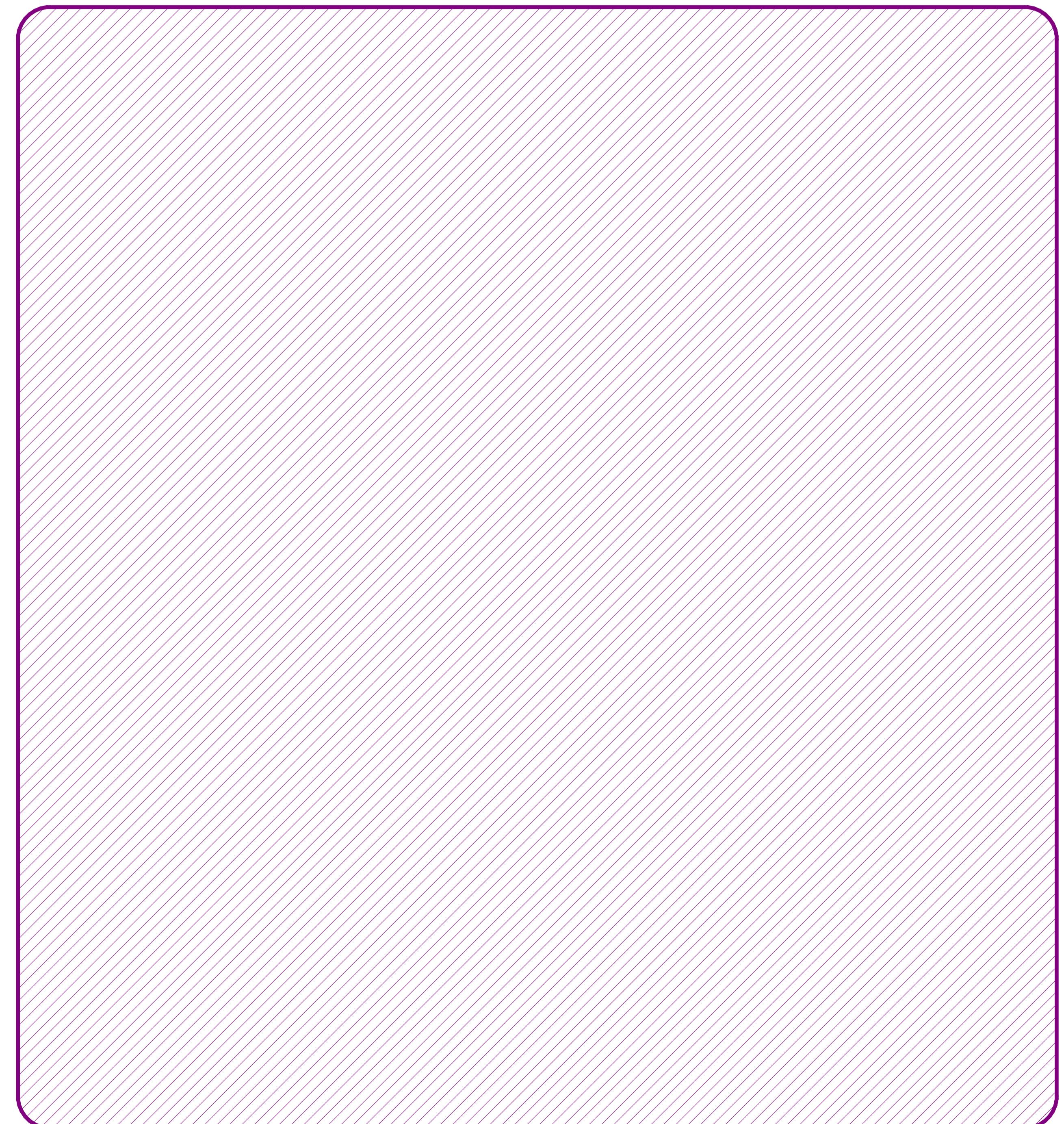
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Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
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AERO

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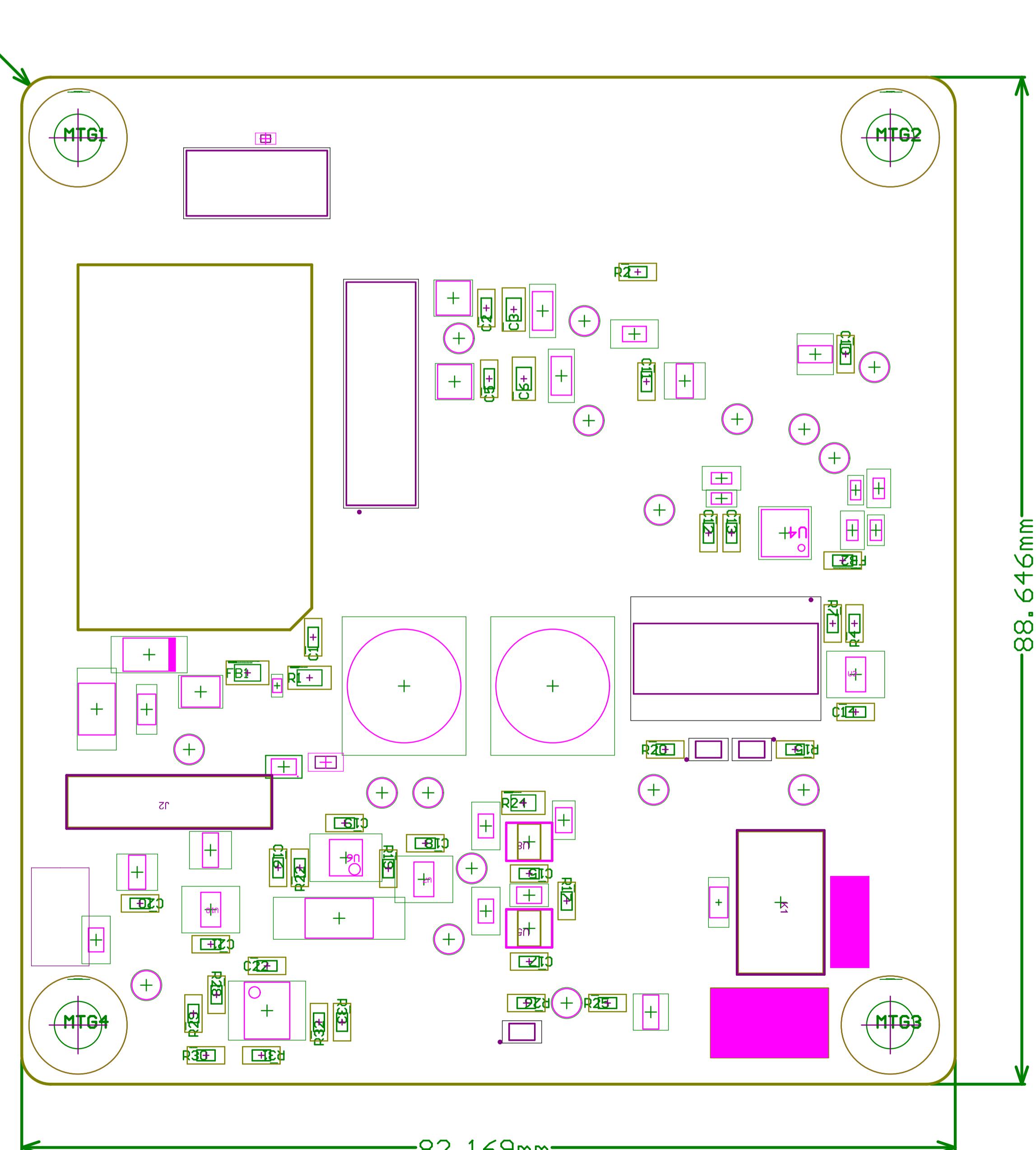
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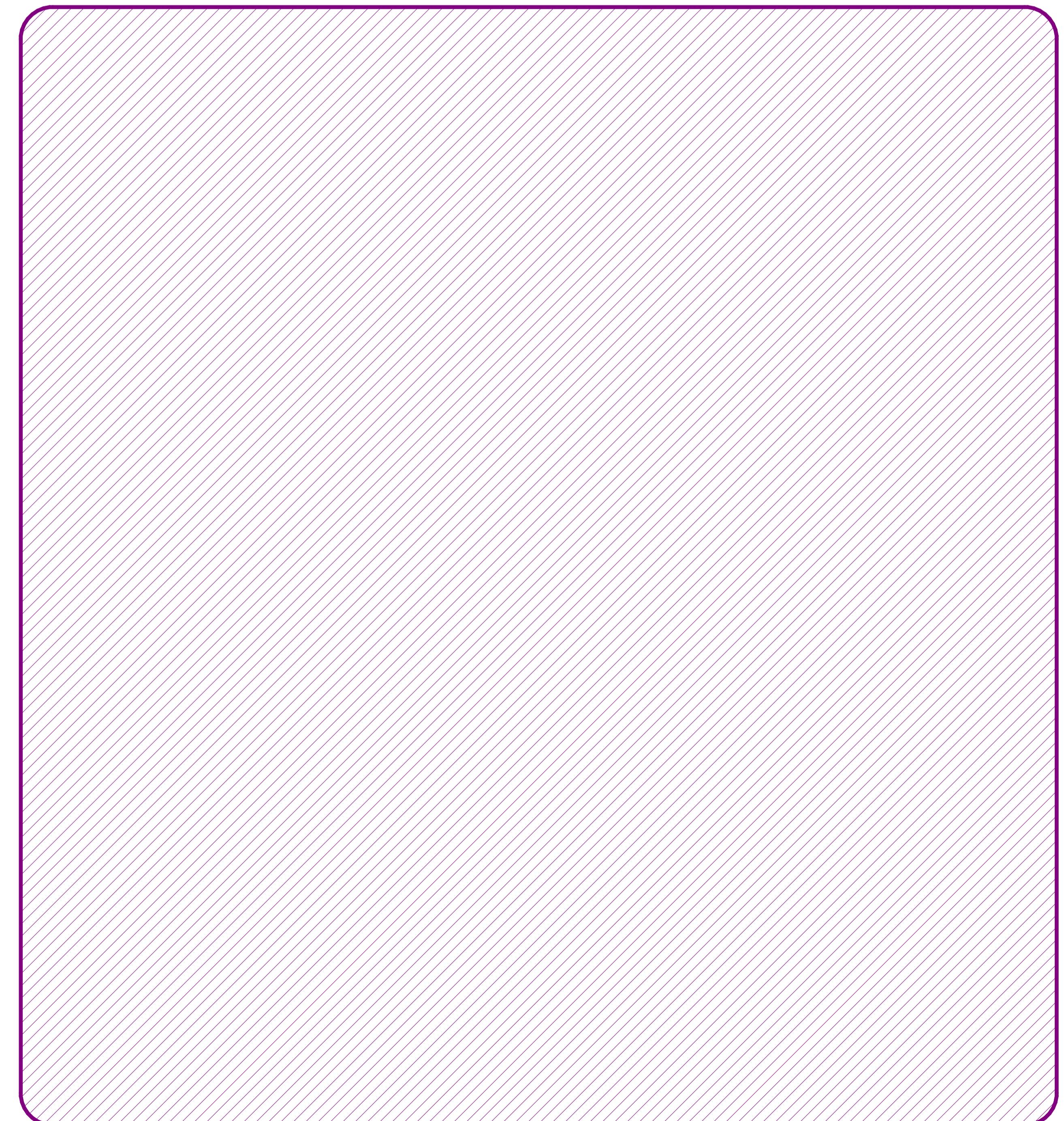
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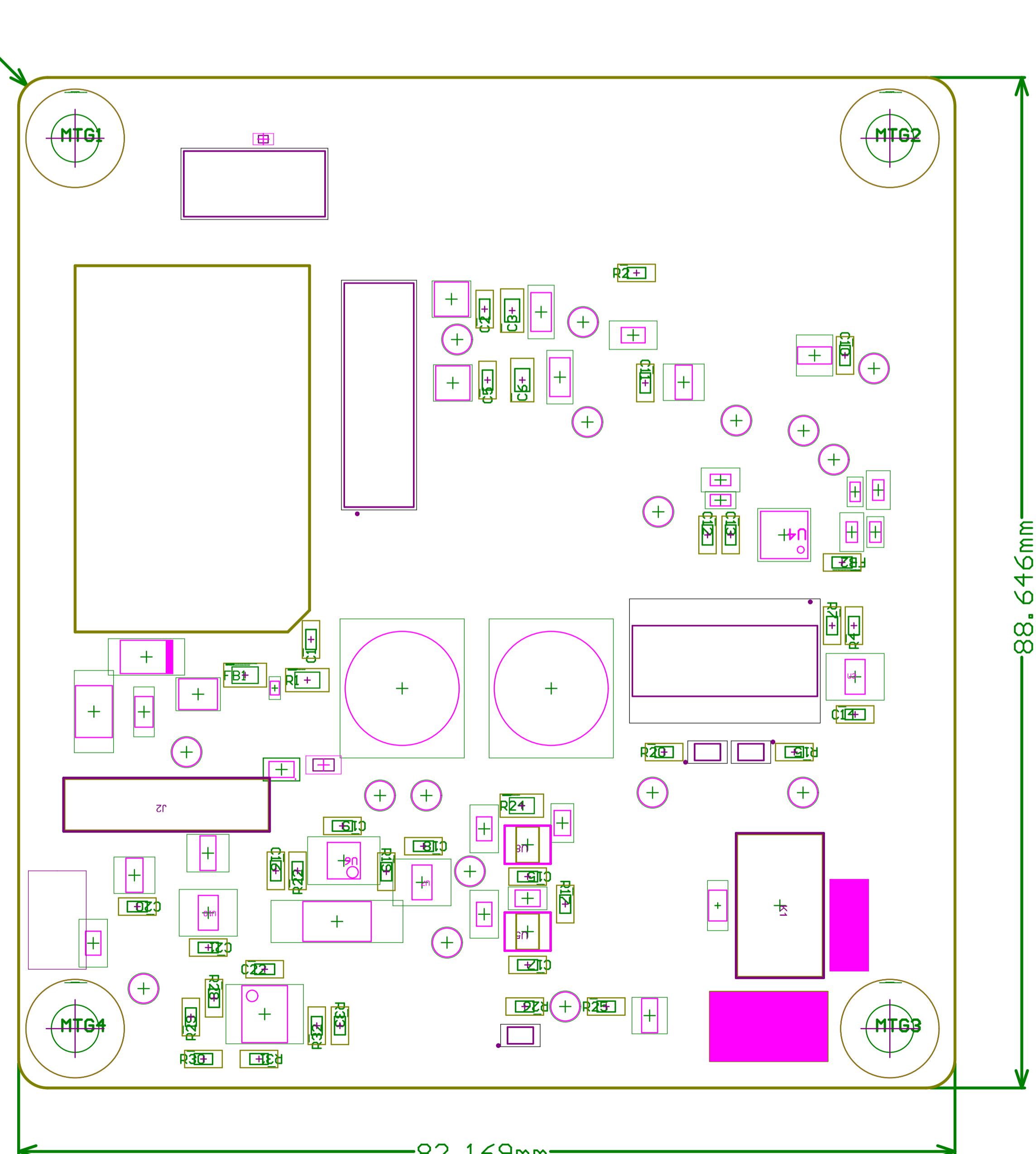
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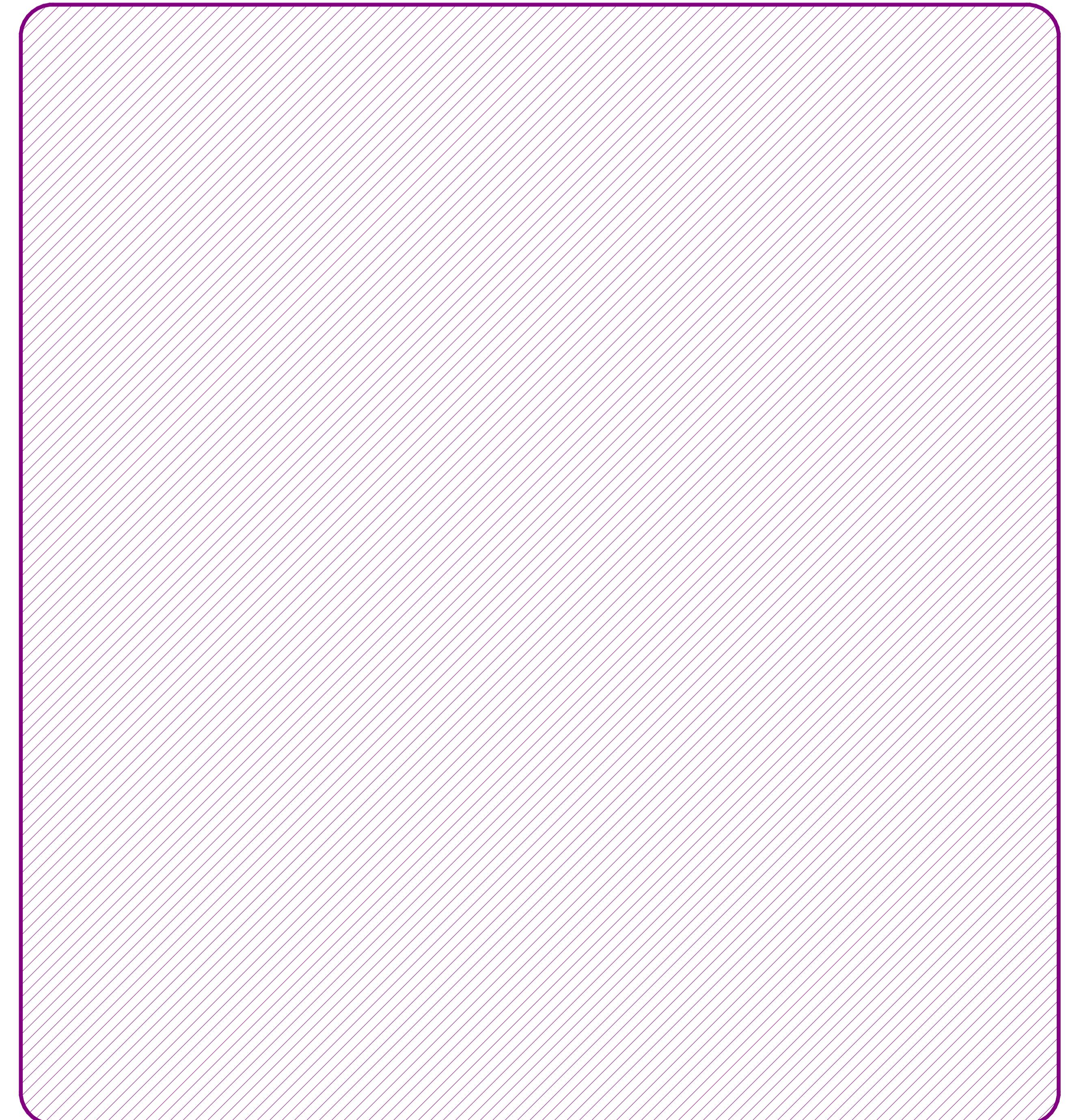
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AERO

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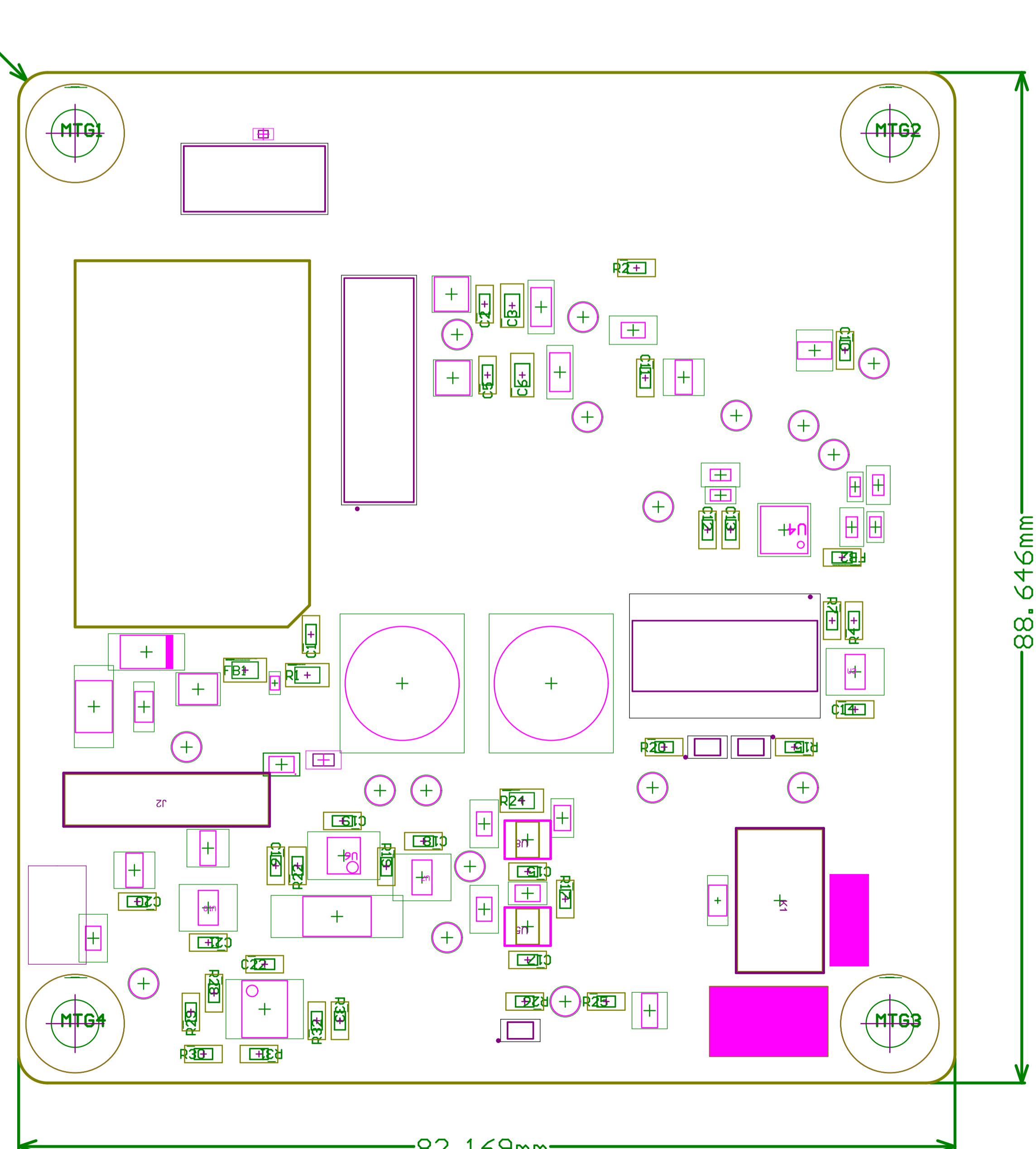
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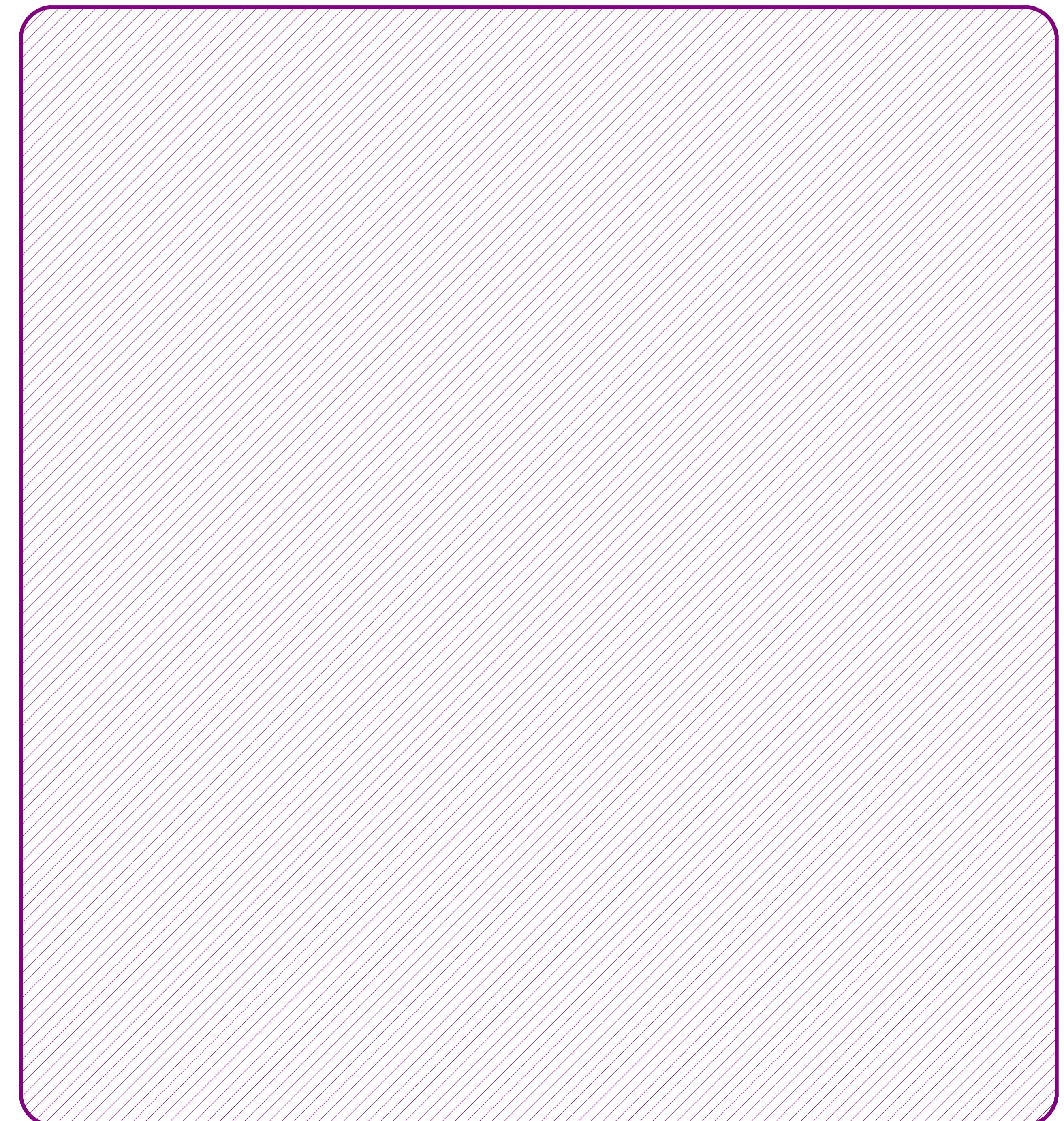
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**AERO**

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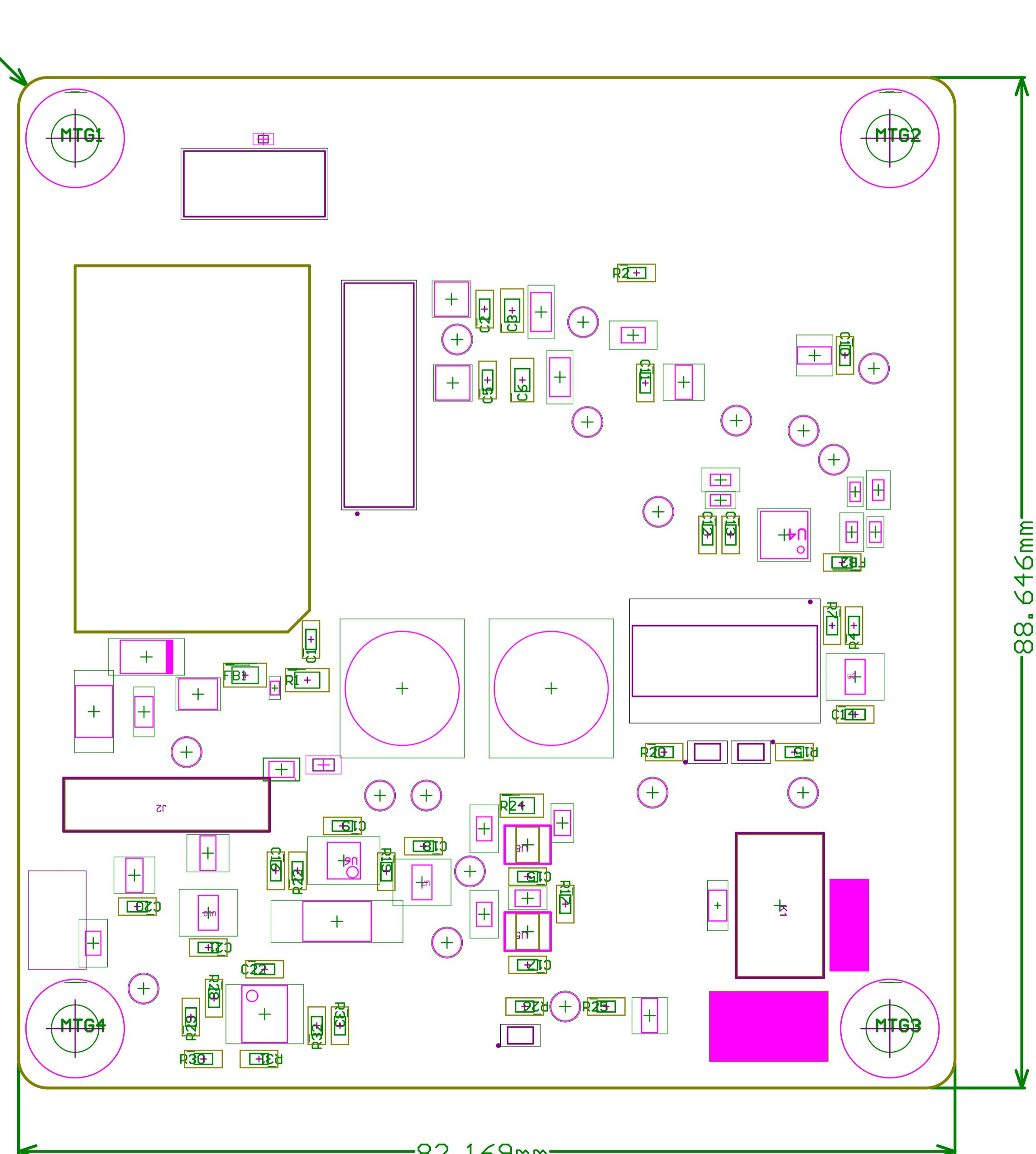
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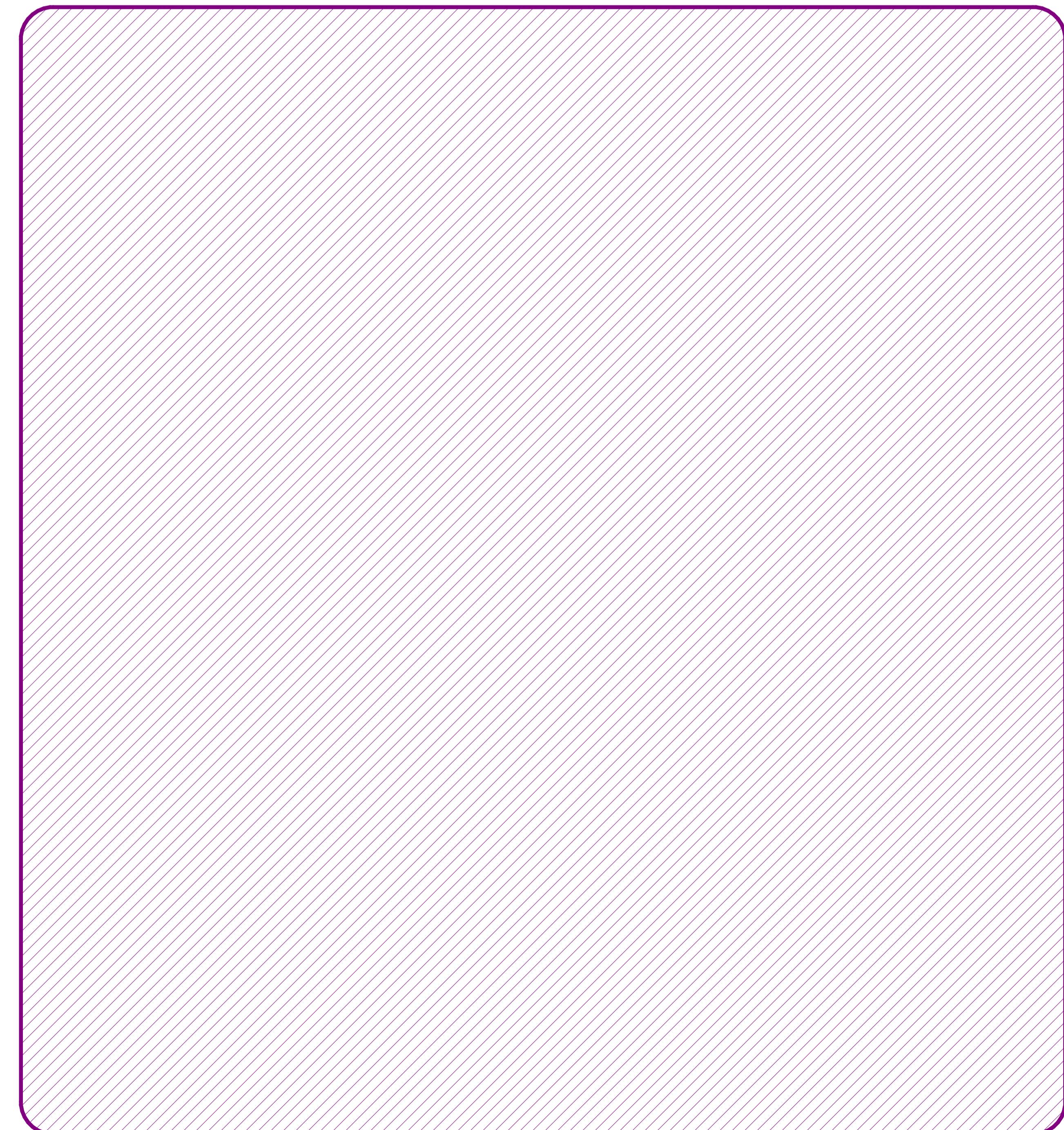
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Andrew Katz  
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**AERO**

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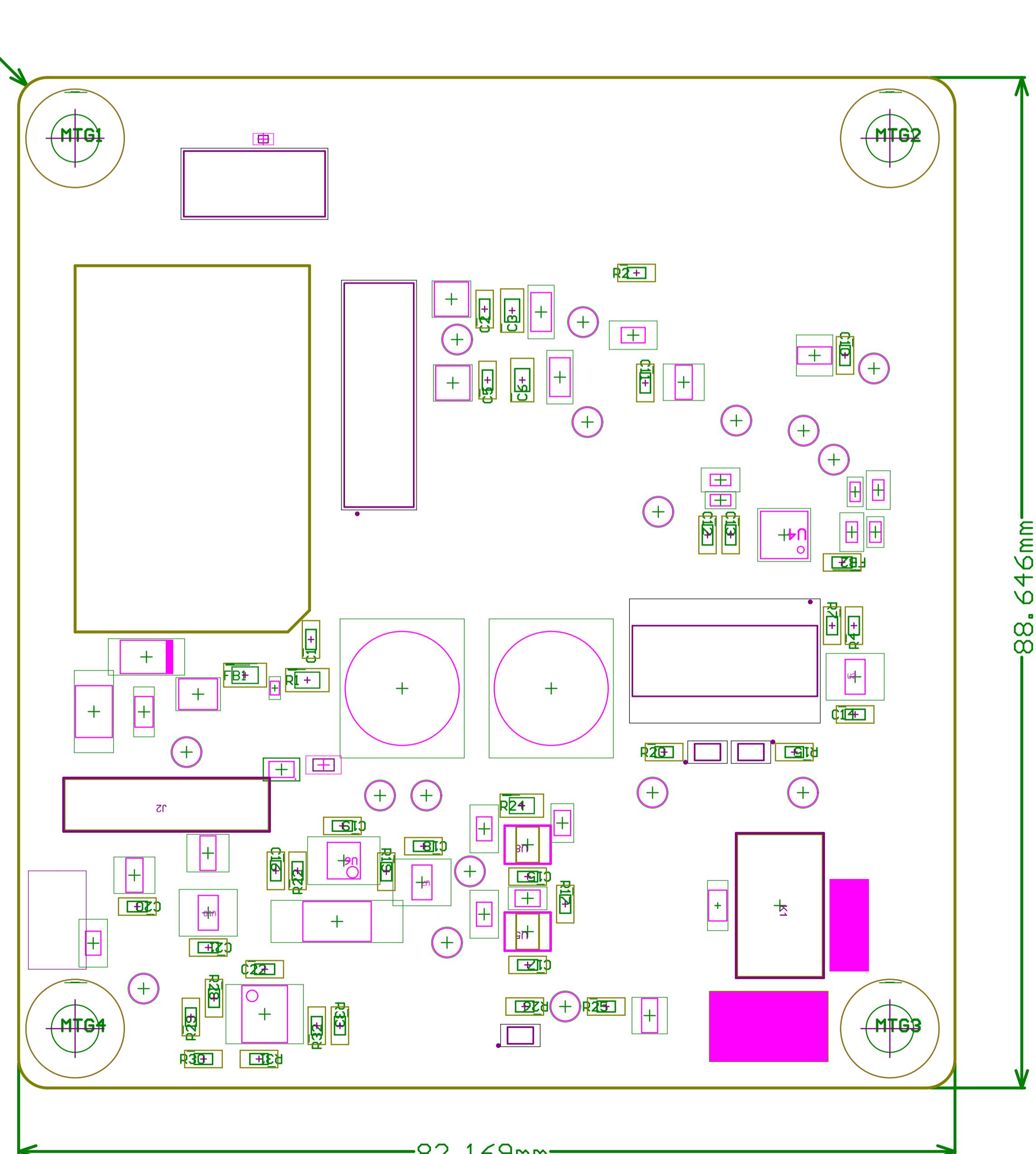
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Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
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	Bottom Overlay				GBO	

Total board thickness: 62.80mil

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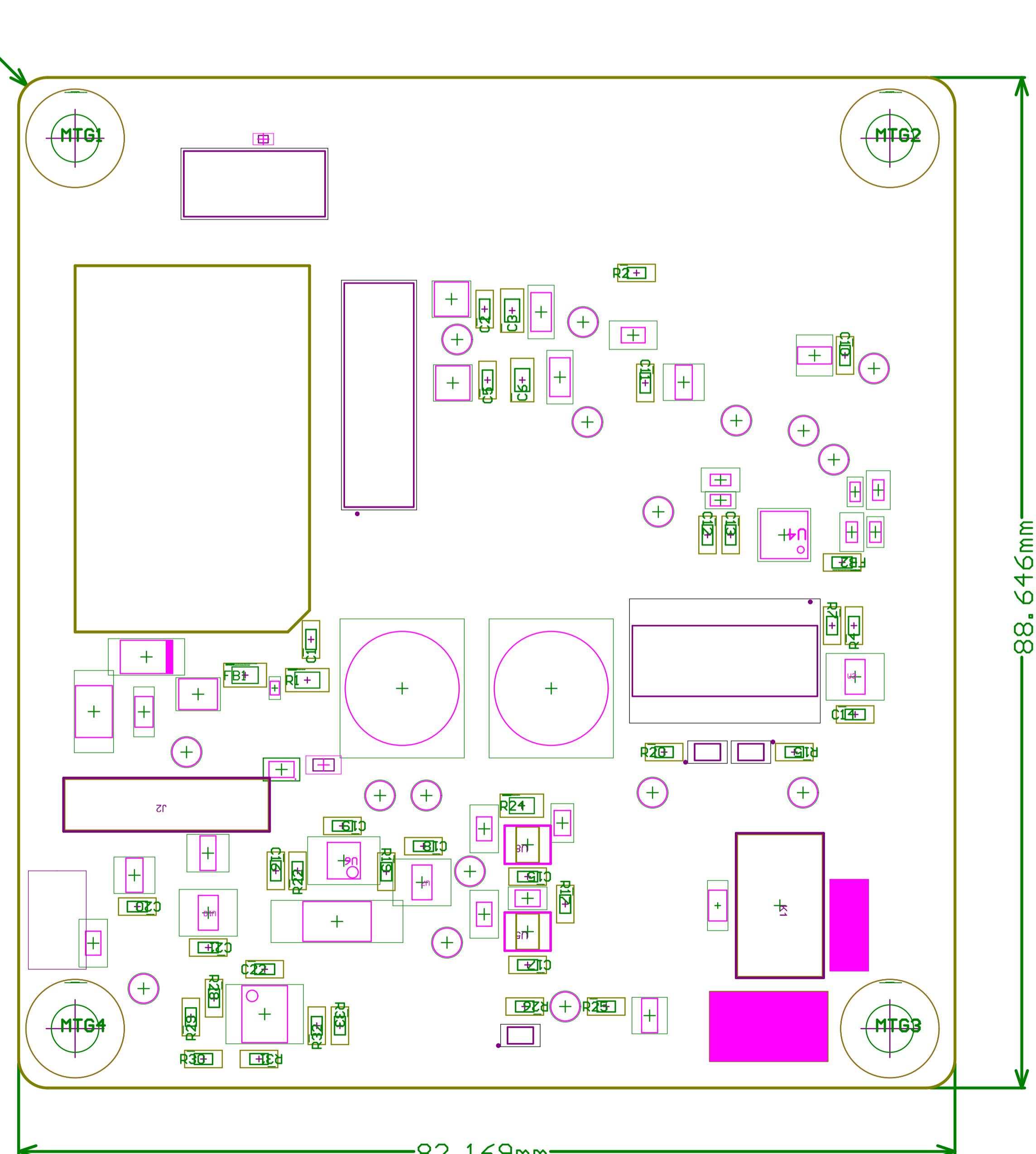
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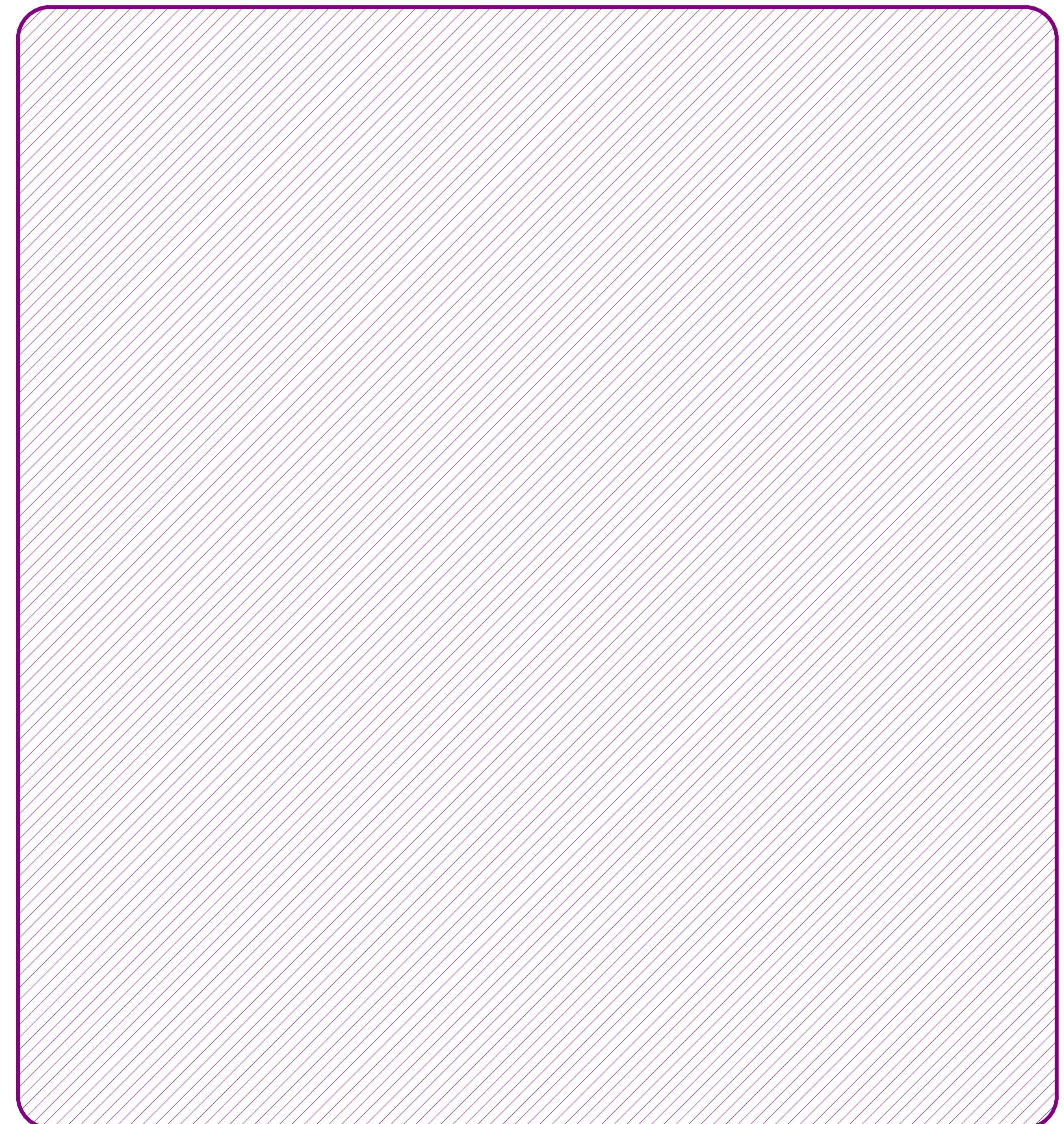
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Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
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Andrew Katz  
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AERO

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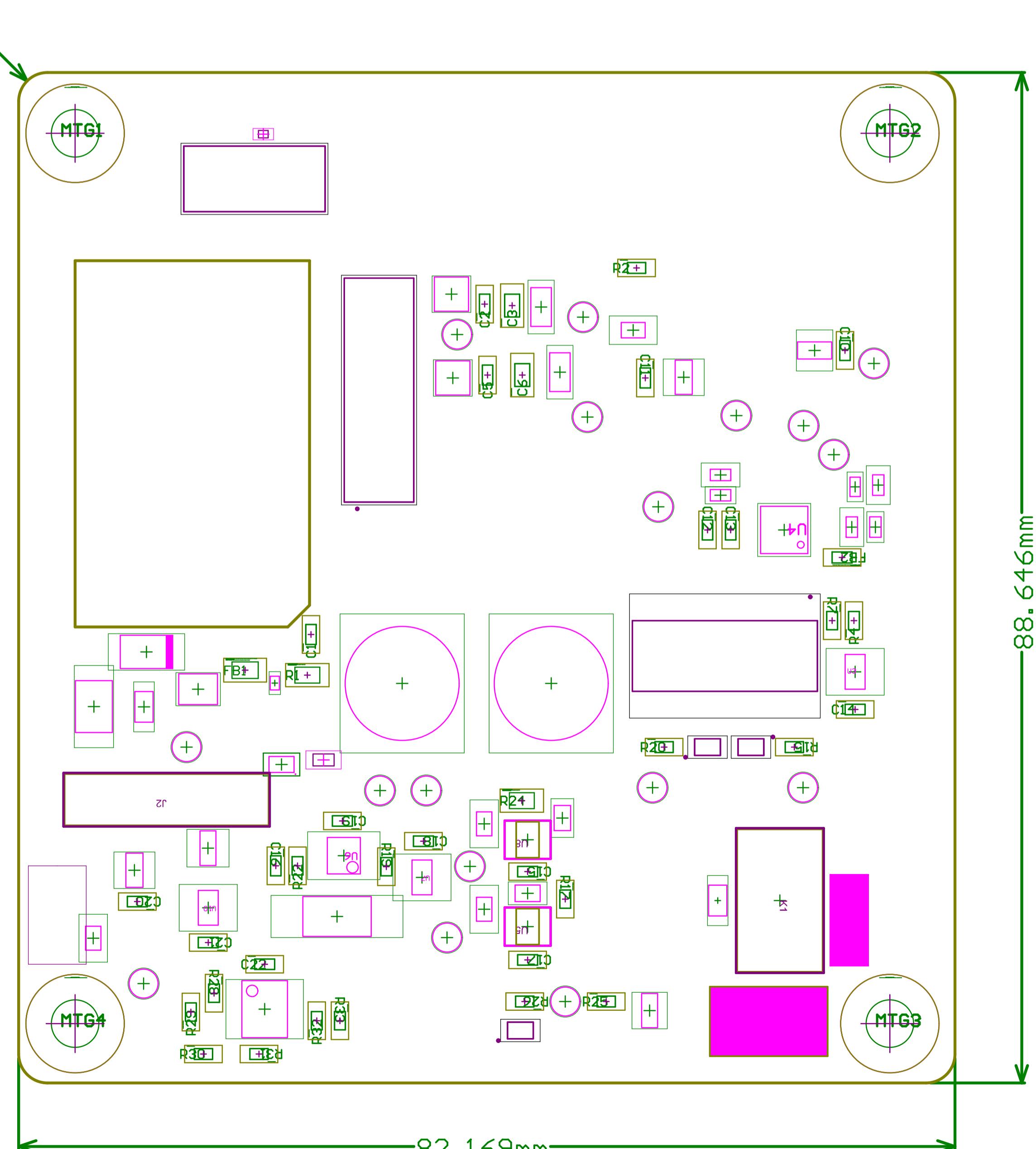
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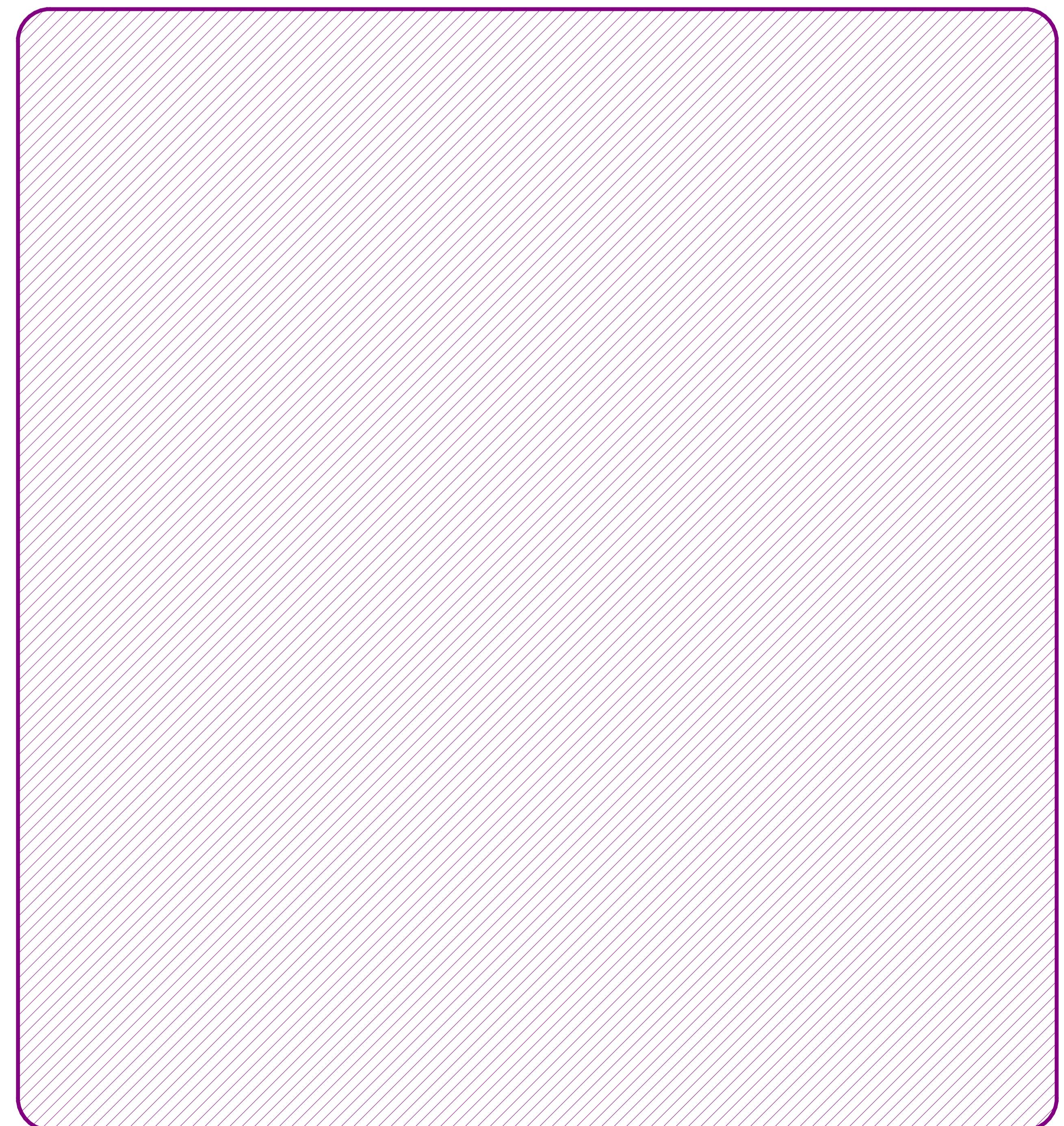
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AERO

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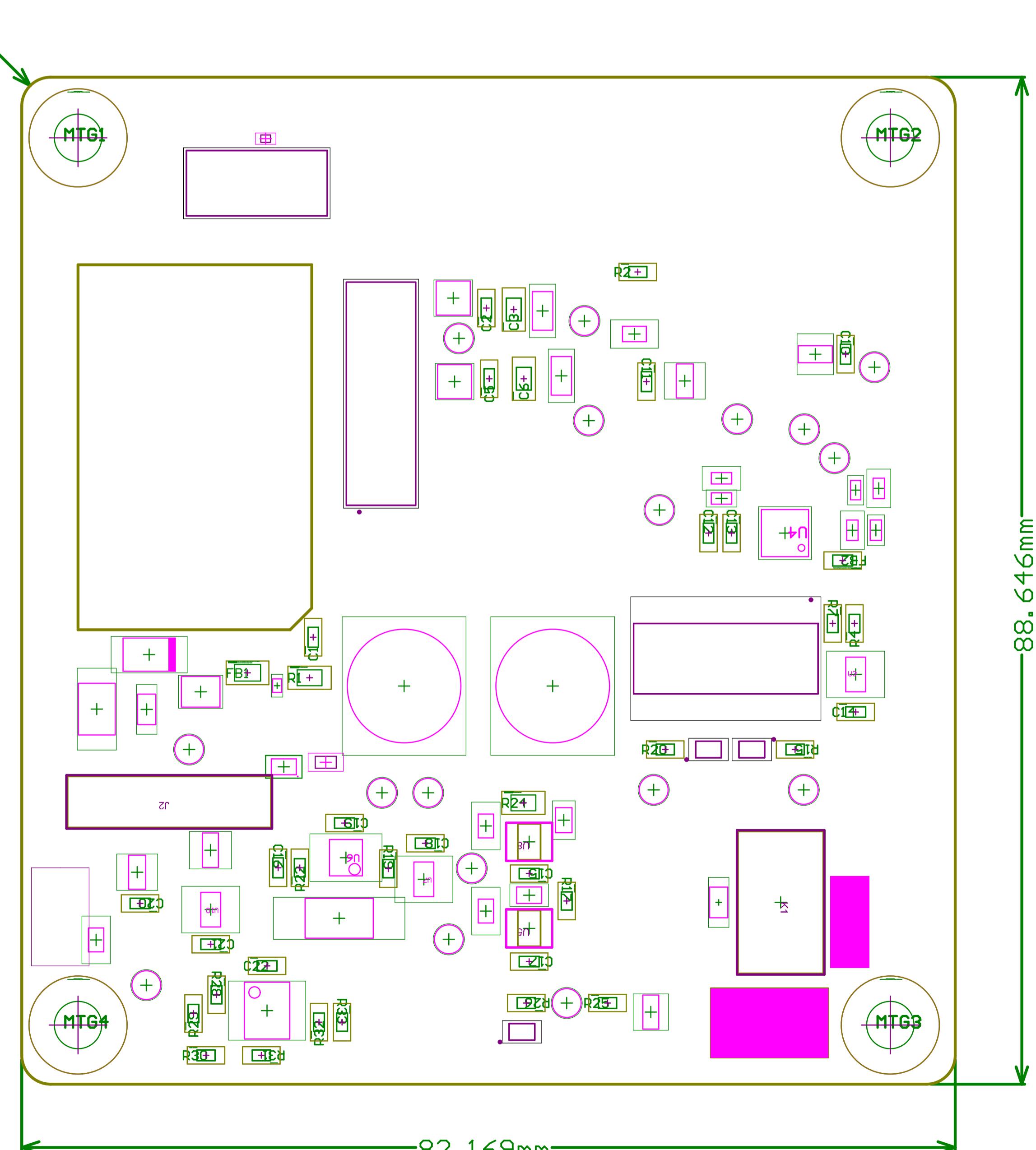
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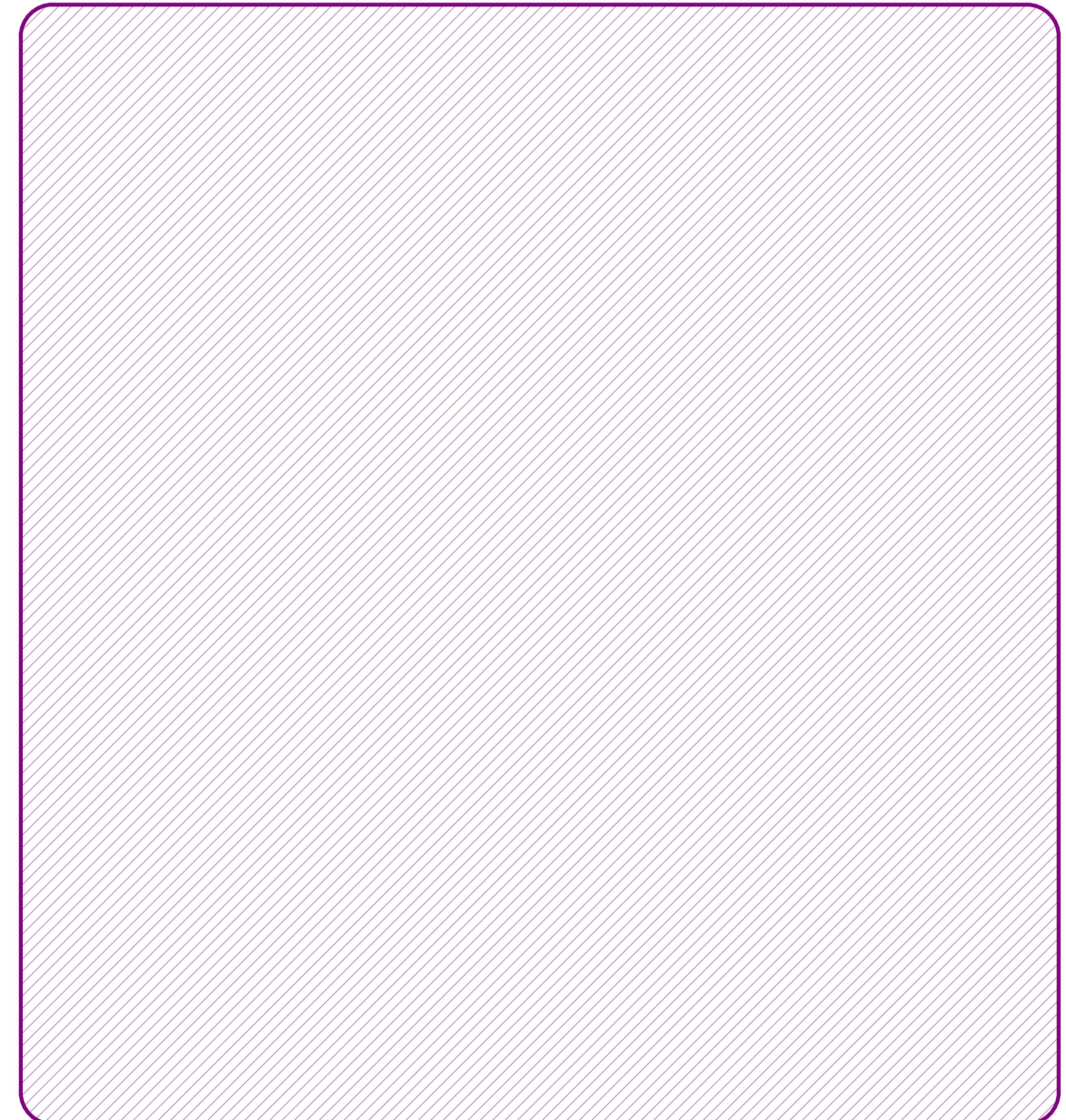
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AERO

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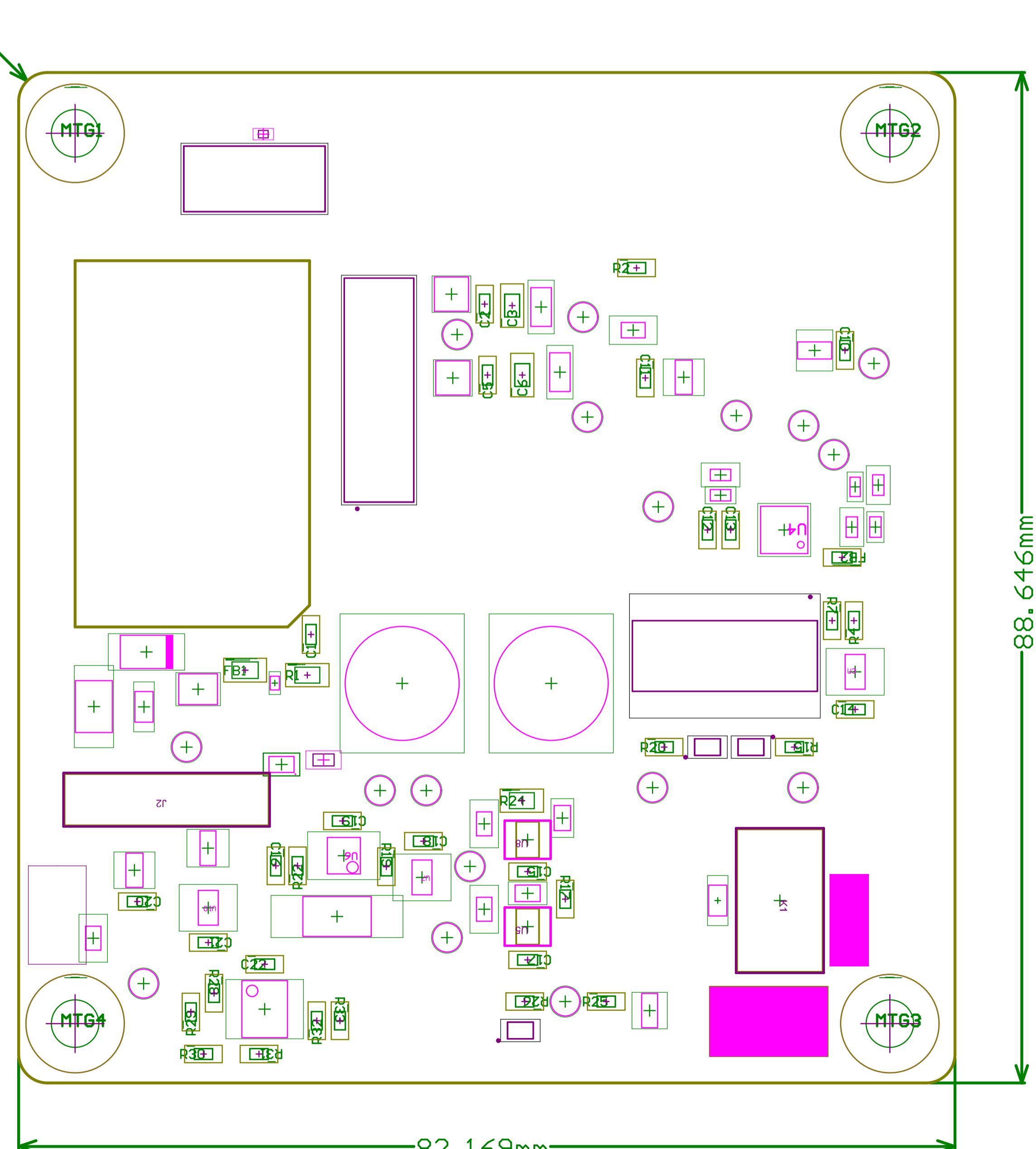
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AEIRO

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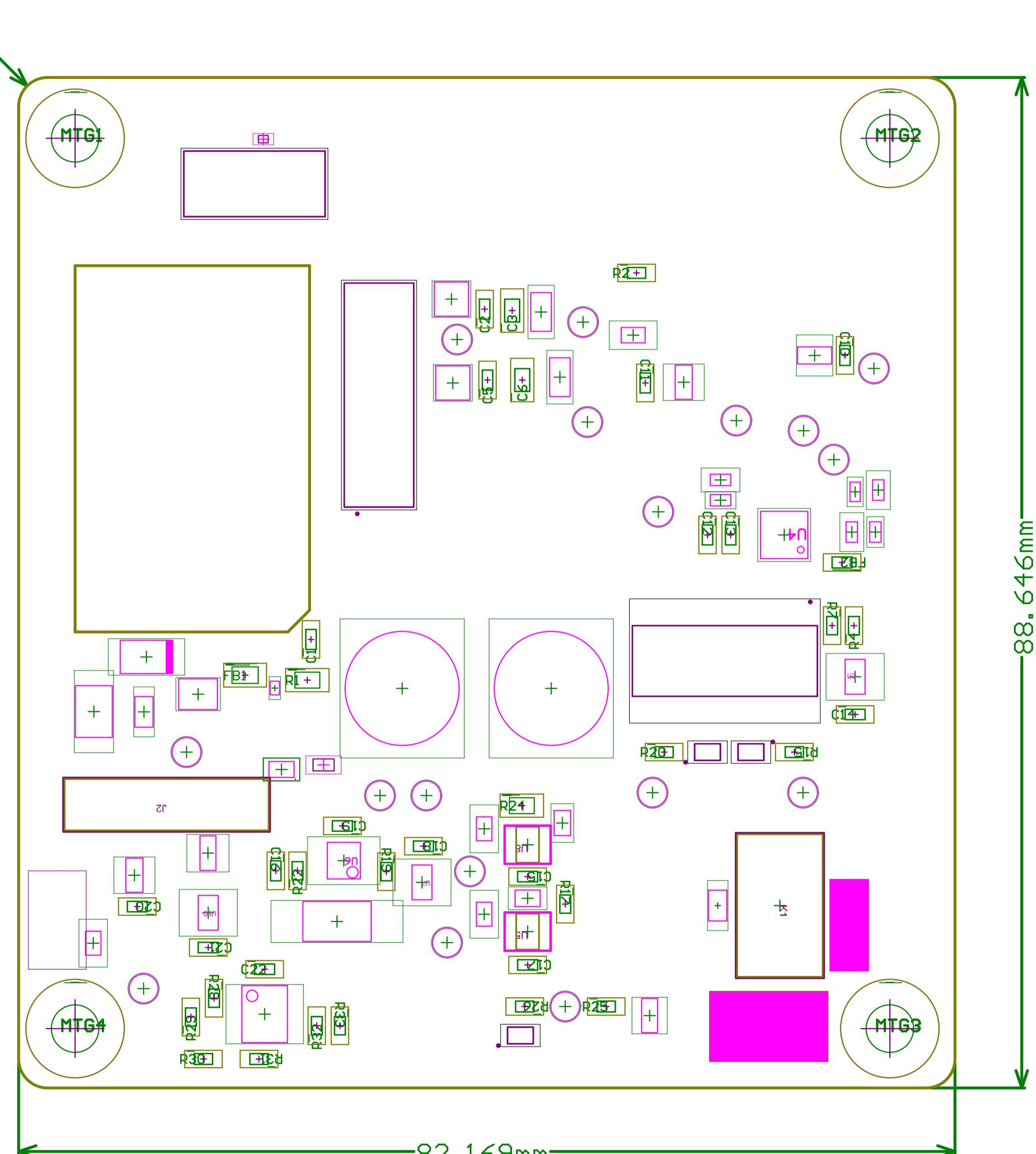
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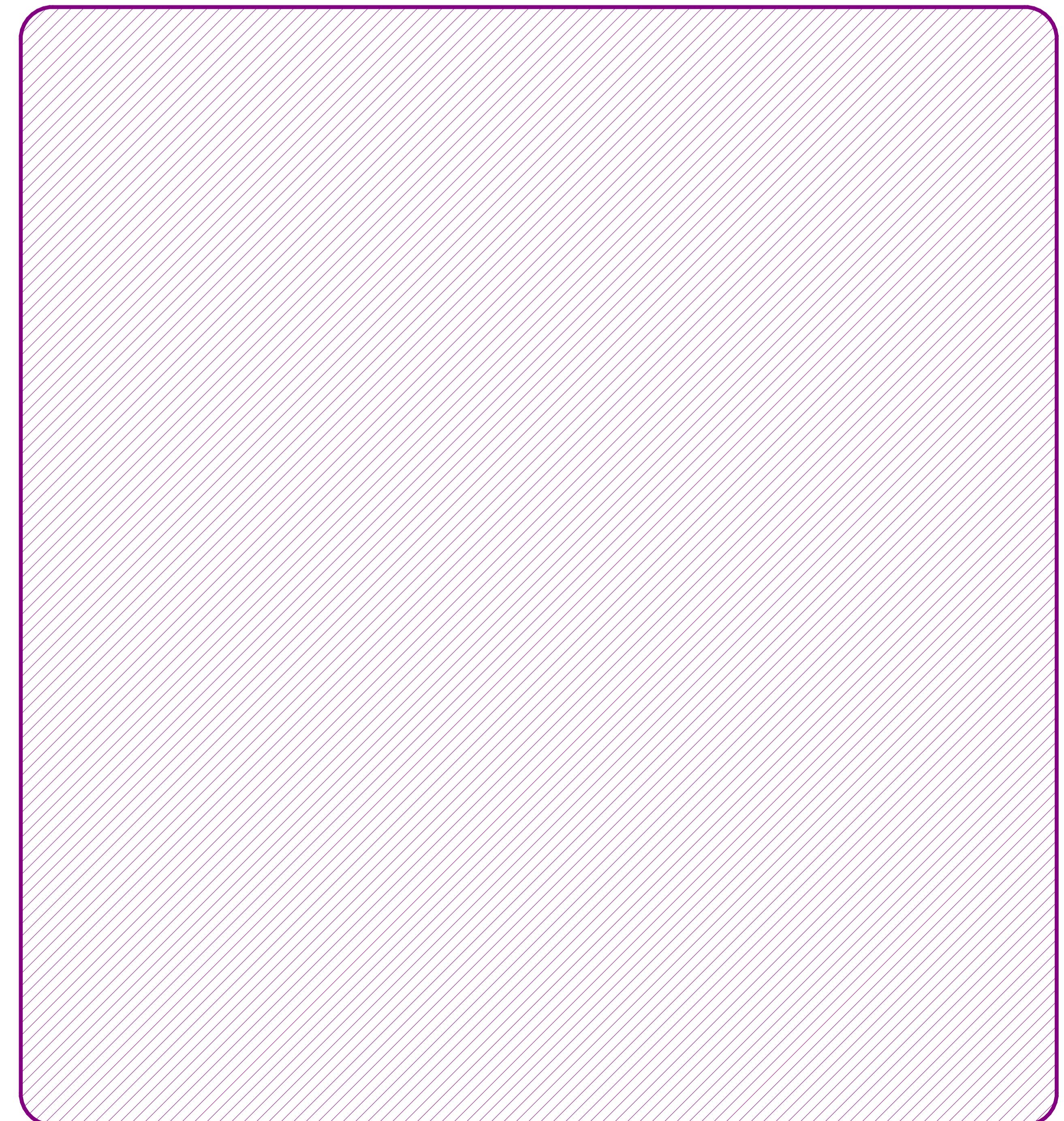
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AEIRO

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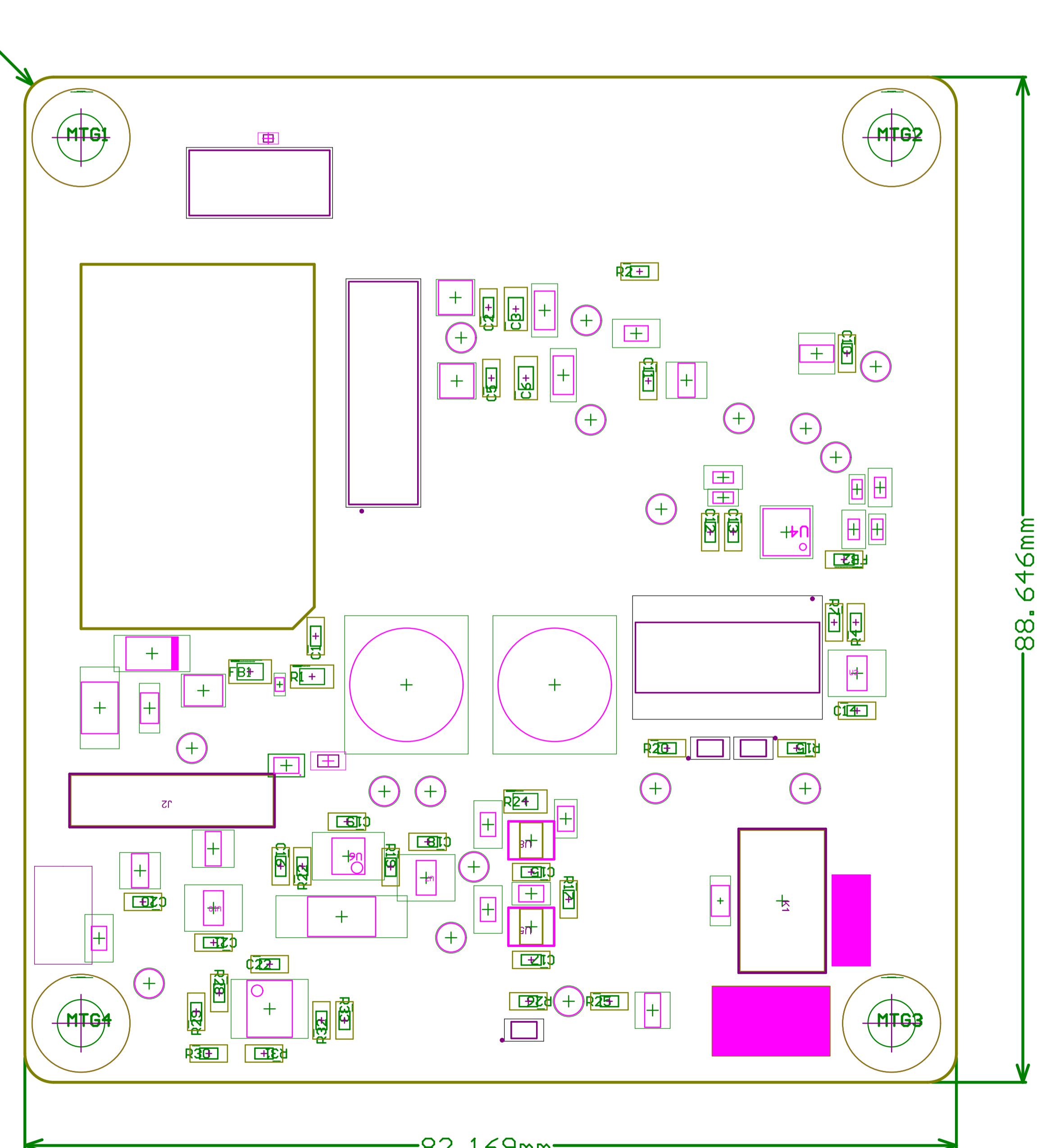
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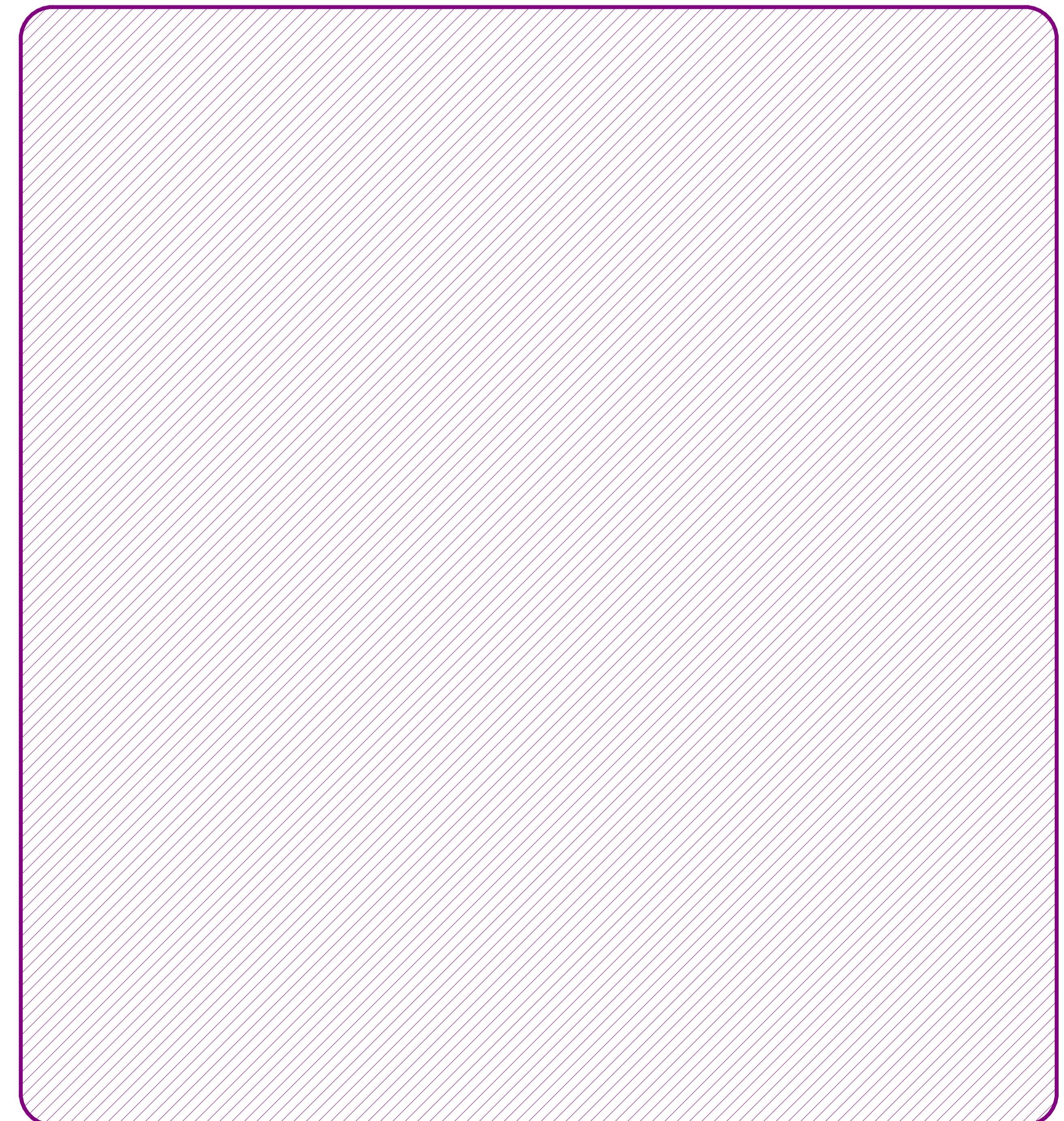
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AERO

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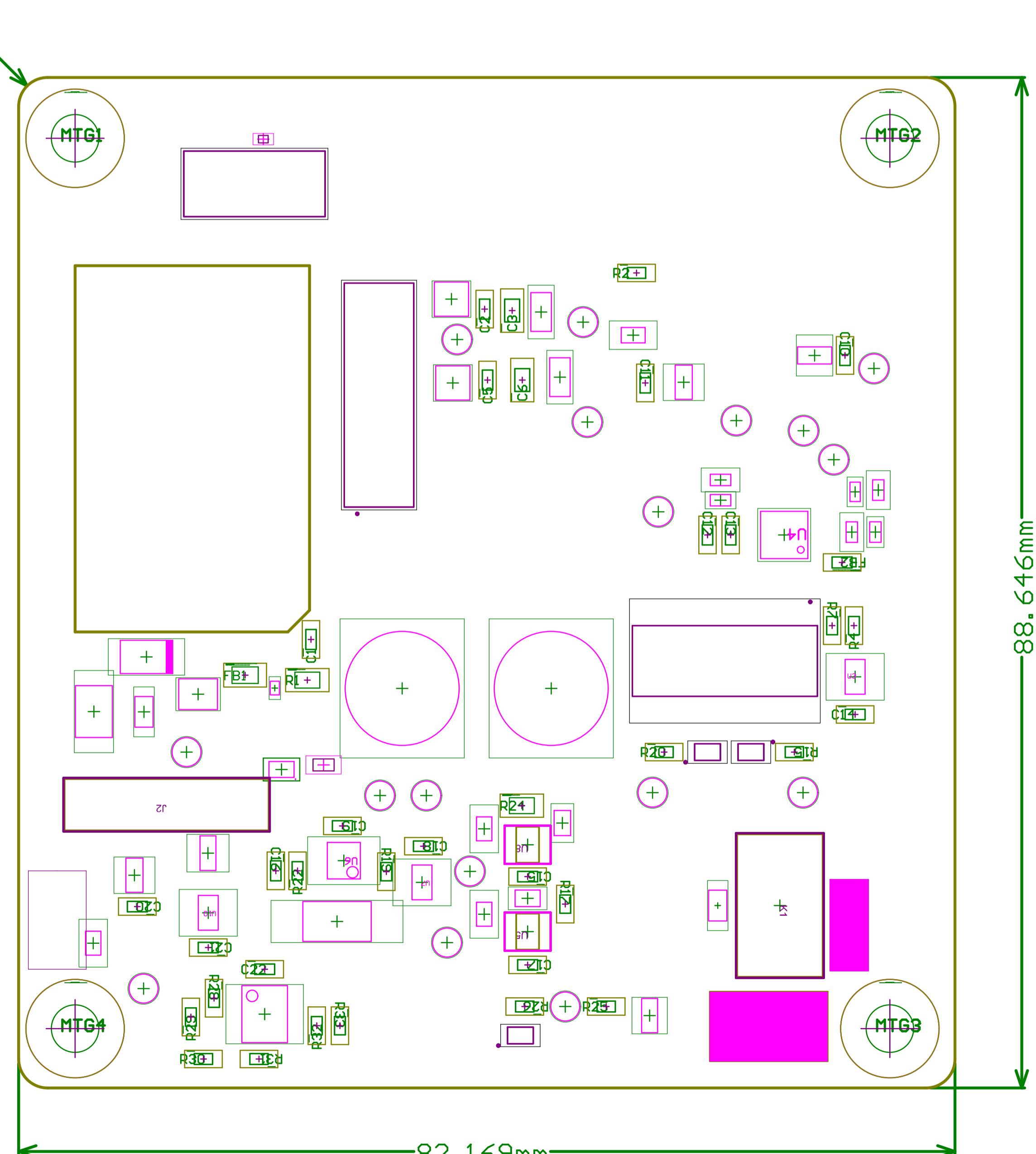
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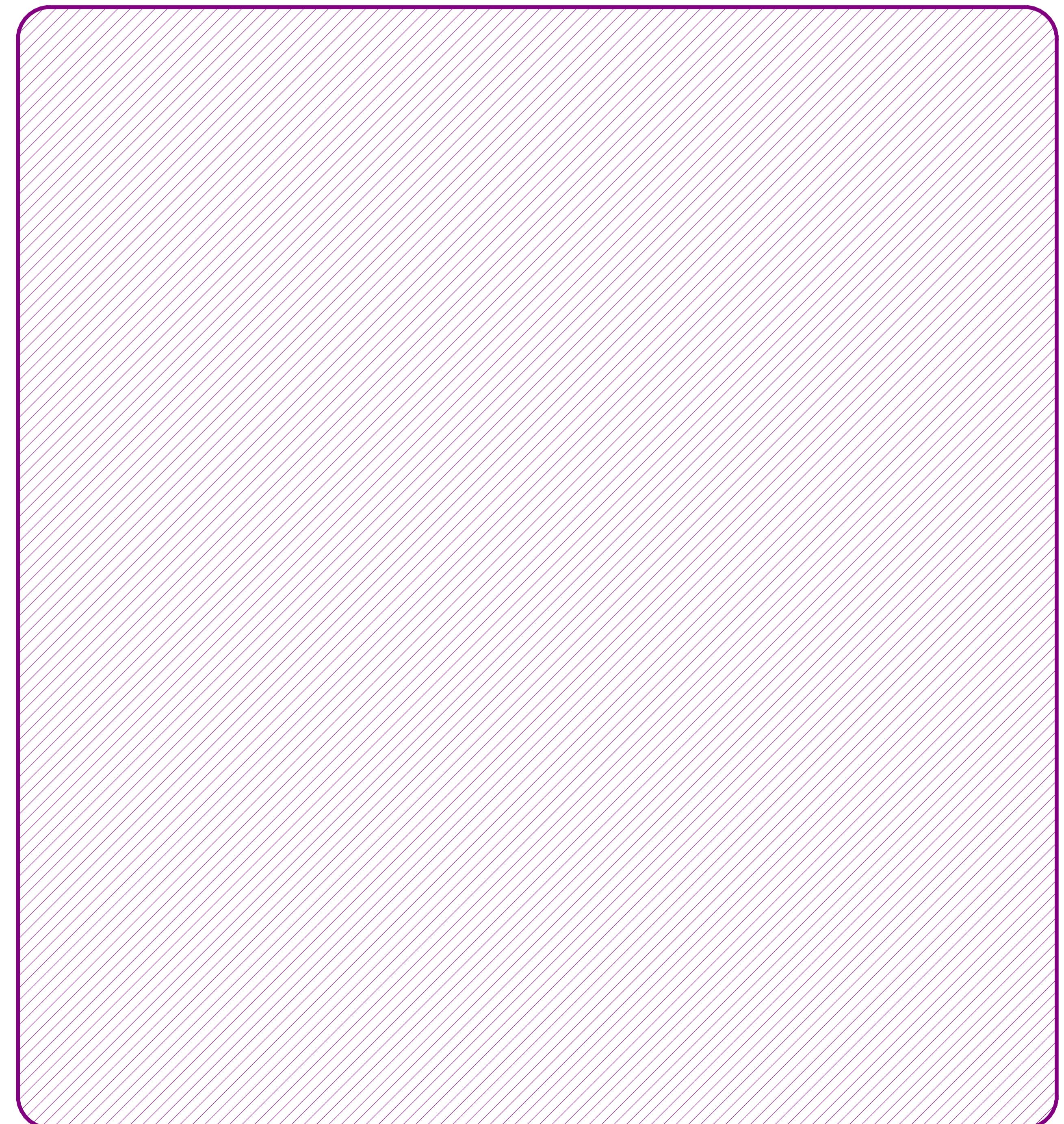
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AERO

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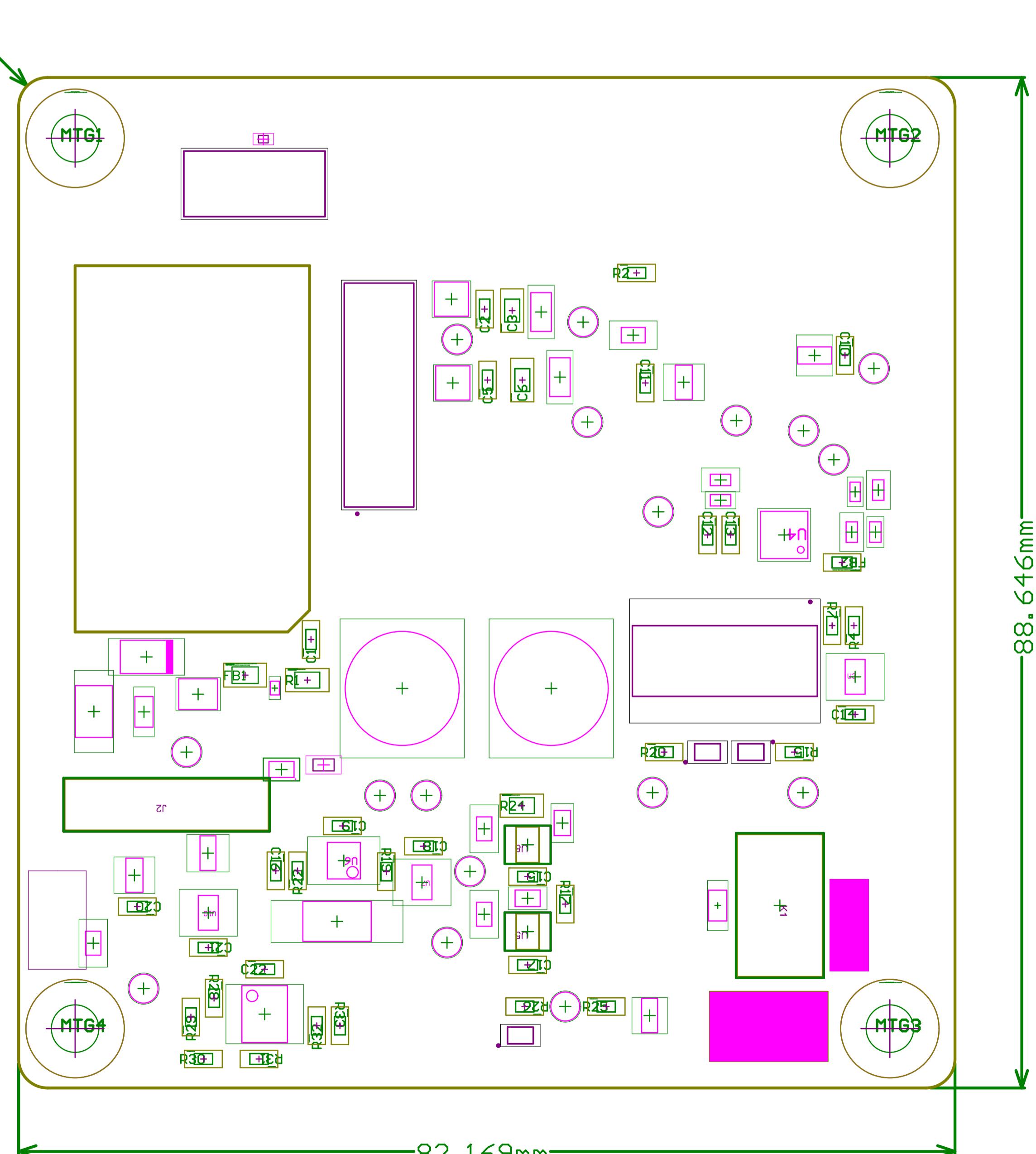
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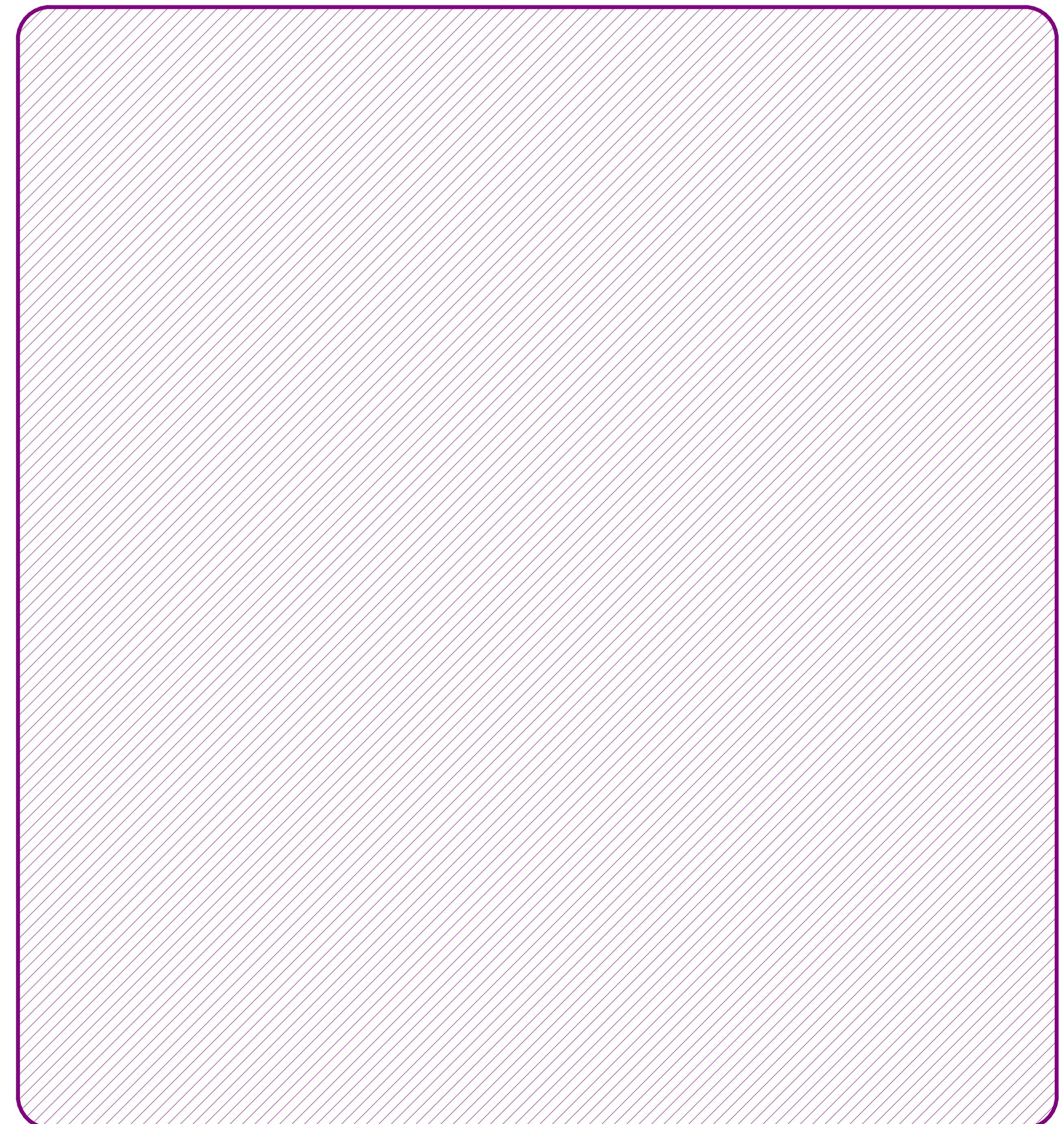
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Date: 2/5/2020 Time: 2:26:28 PM Sheet 1 of 1

File: UVM AERO BSPD.PcbDoc

Designer:  
Andrew Katz  
aakatz@gmail.com  
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AERO

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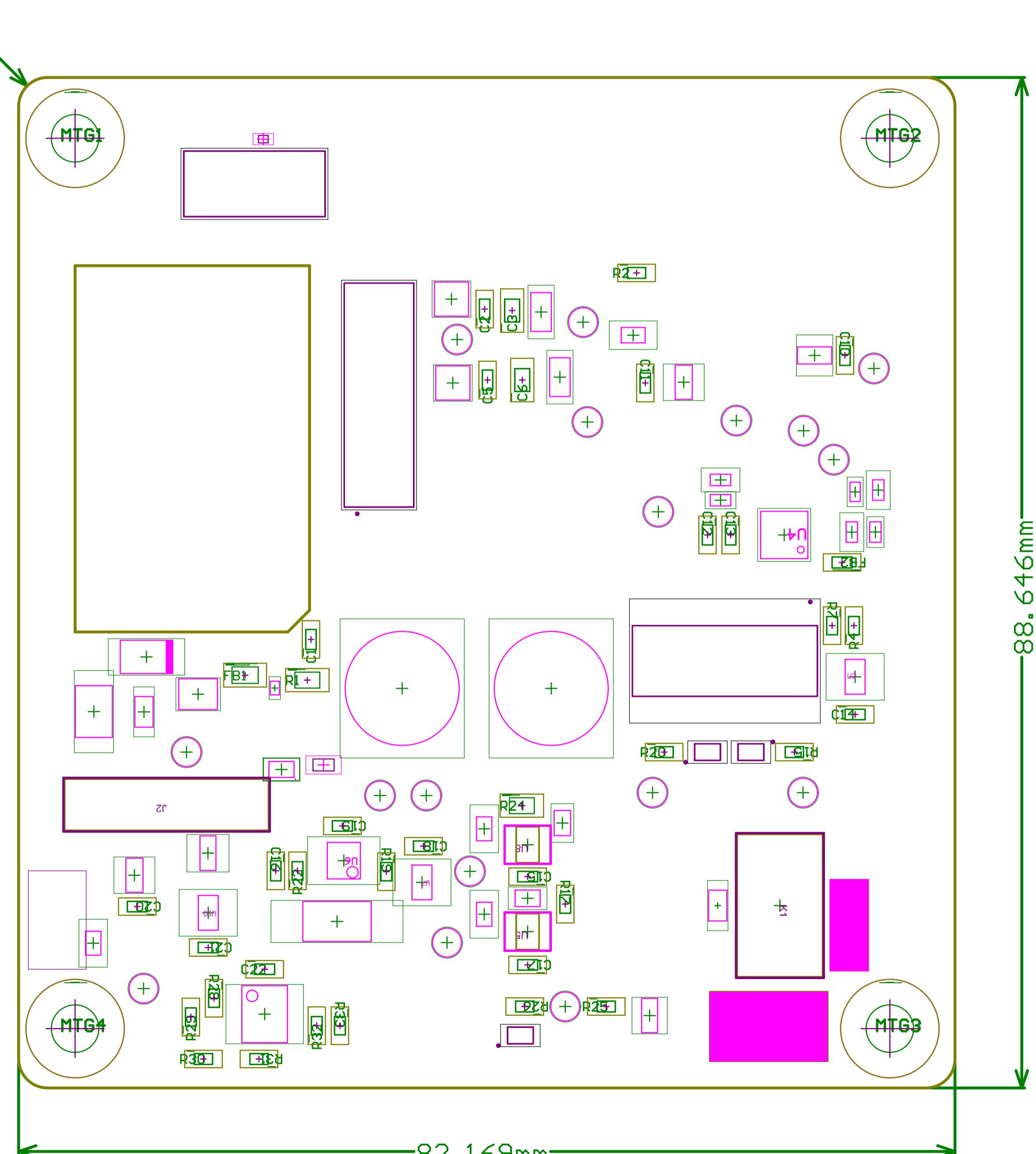
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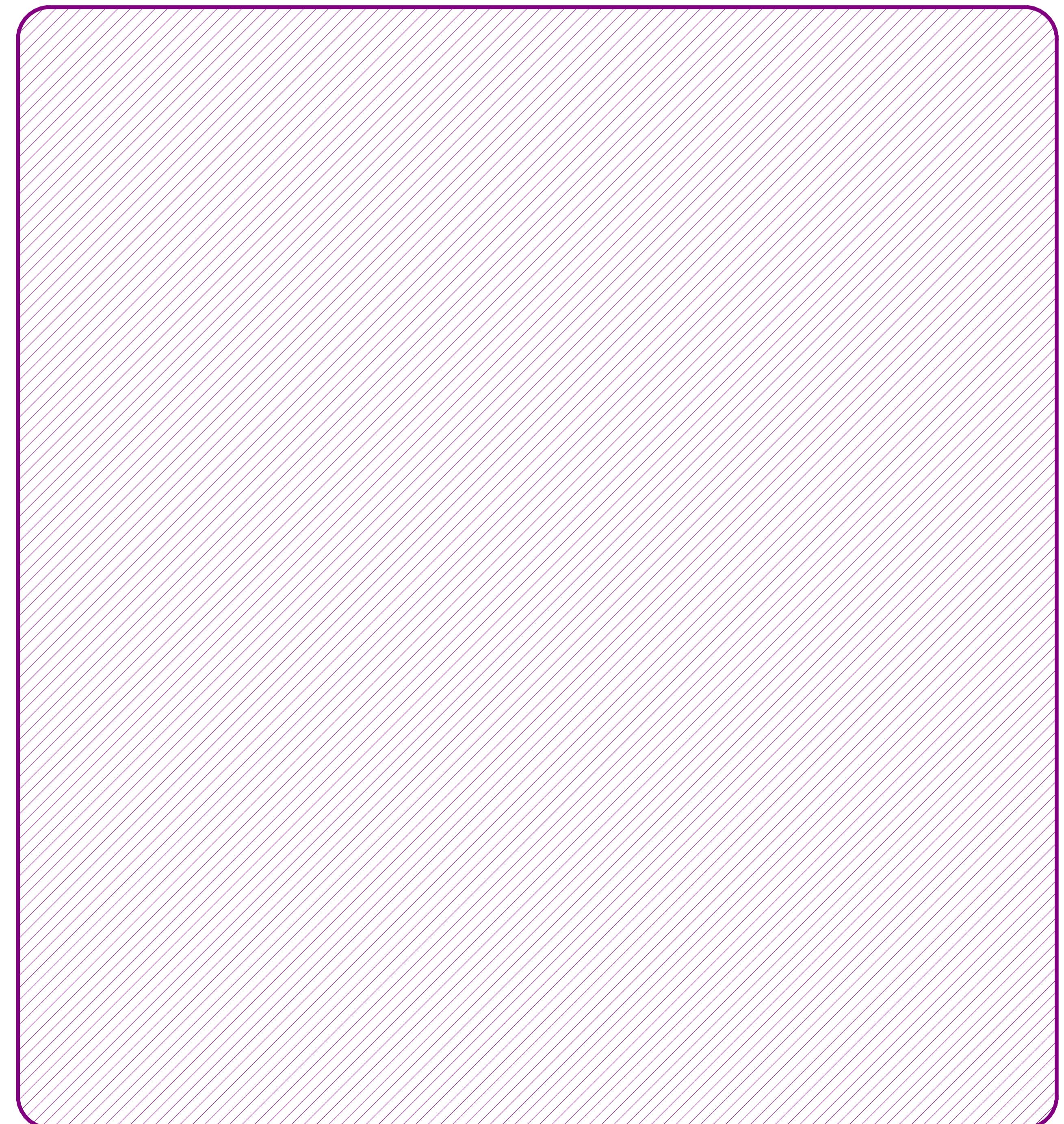
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Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	1.00mil	4	GTS	
1	Top Layer	Copper	1.40mil		GTL	
	Dielectric 1	FR-4	58.00mil	4.2		
2	Bottom Layer	Copper	1.40mil		GBL	
	Bottom Solder	SM-001	1.00mil	4	GBS	
	Bottom Overlay				GBO	

Total board thickness: 62.80mil



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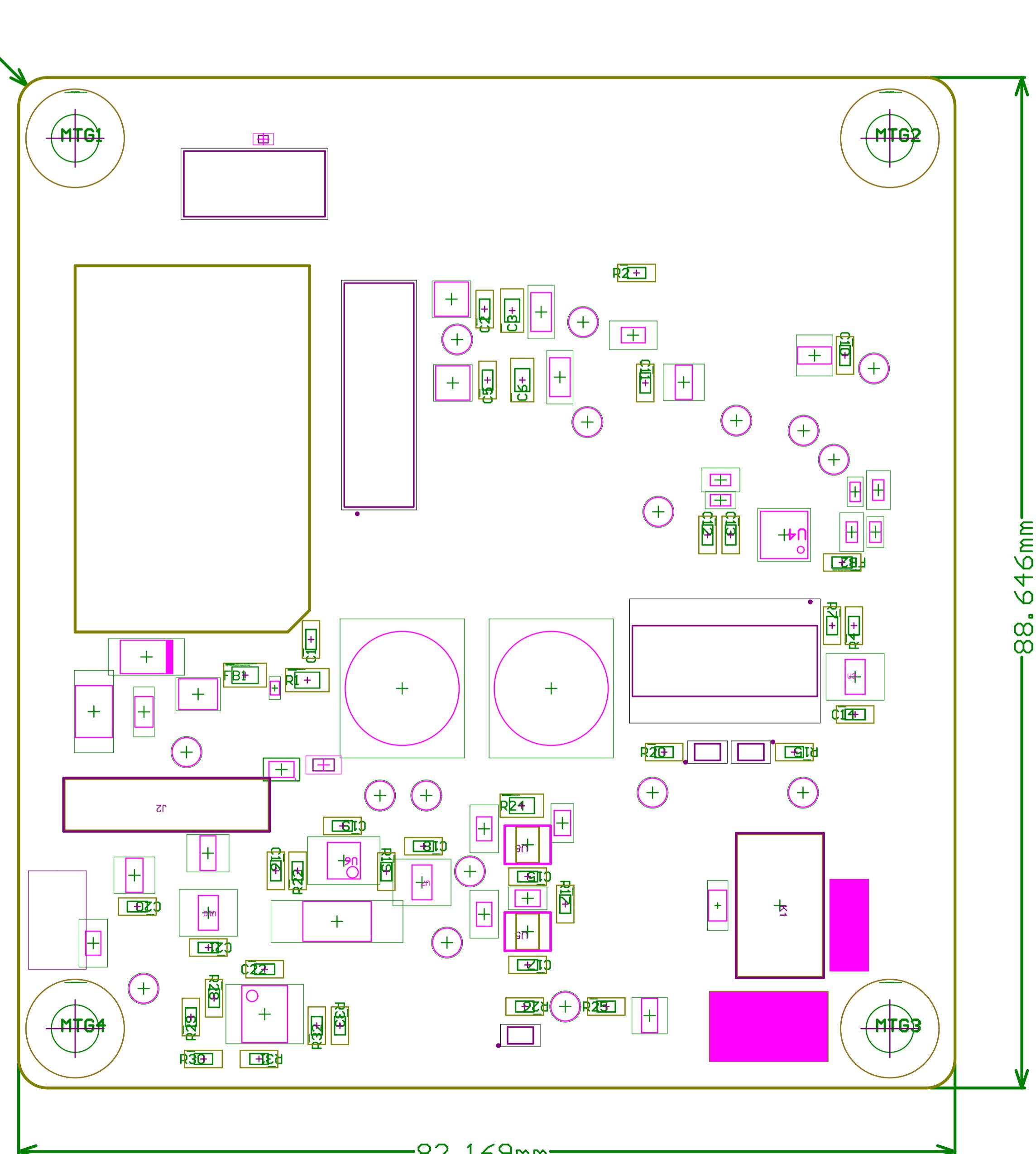
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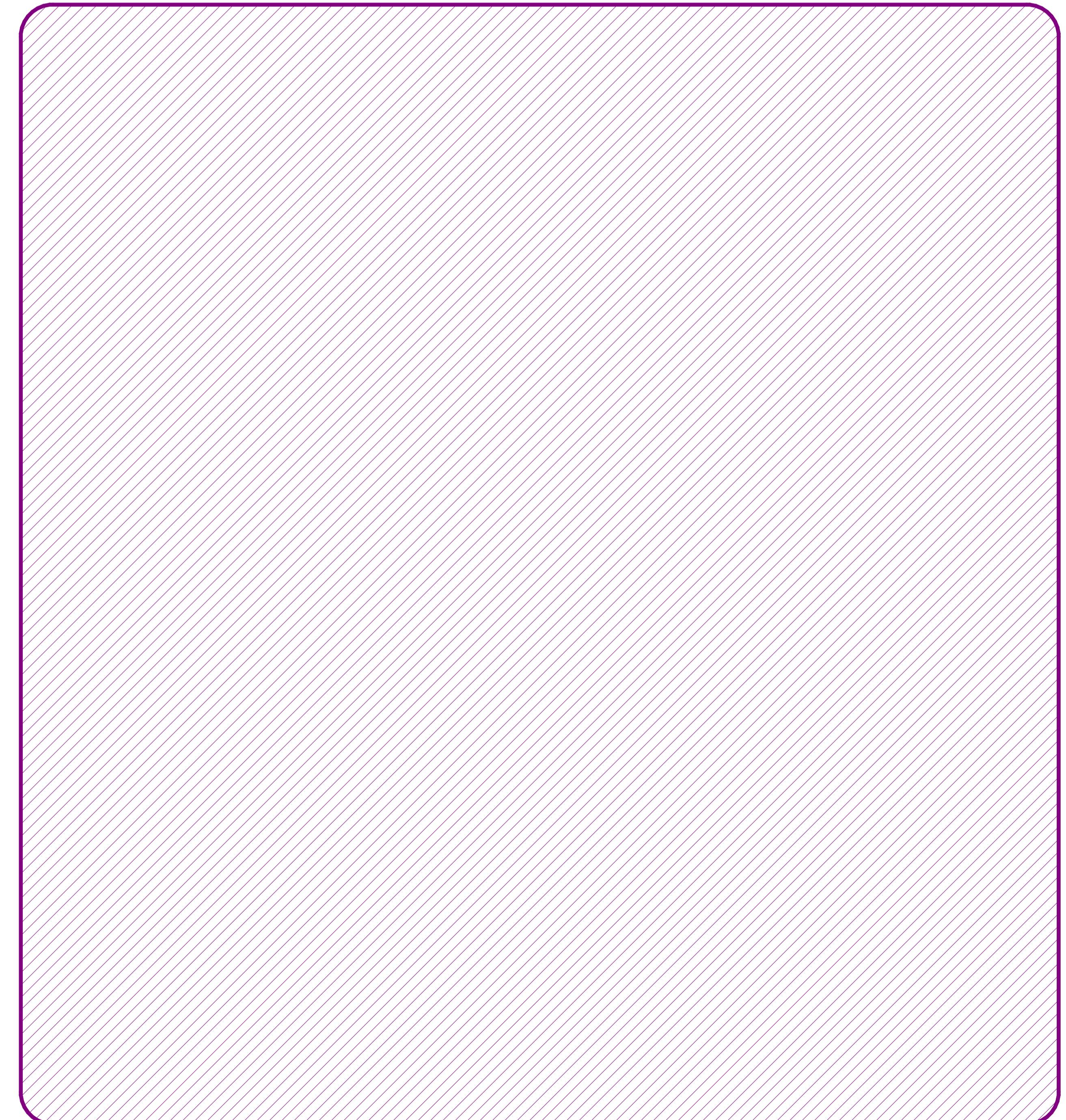
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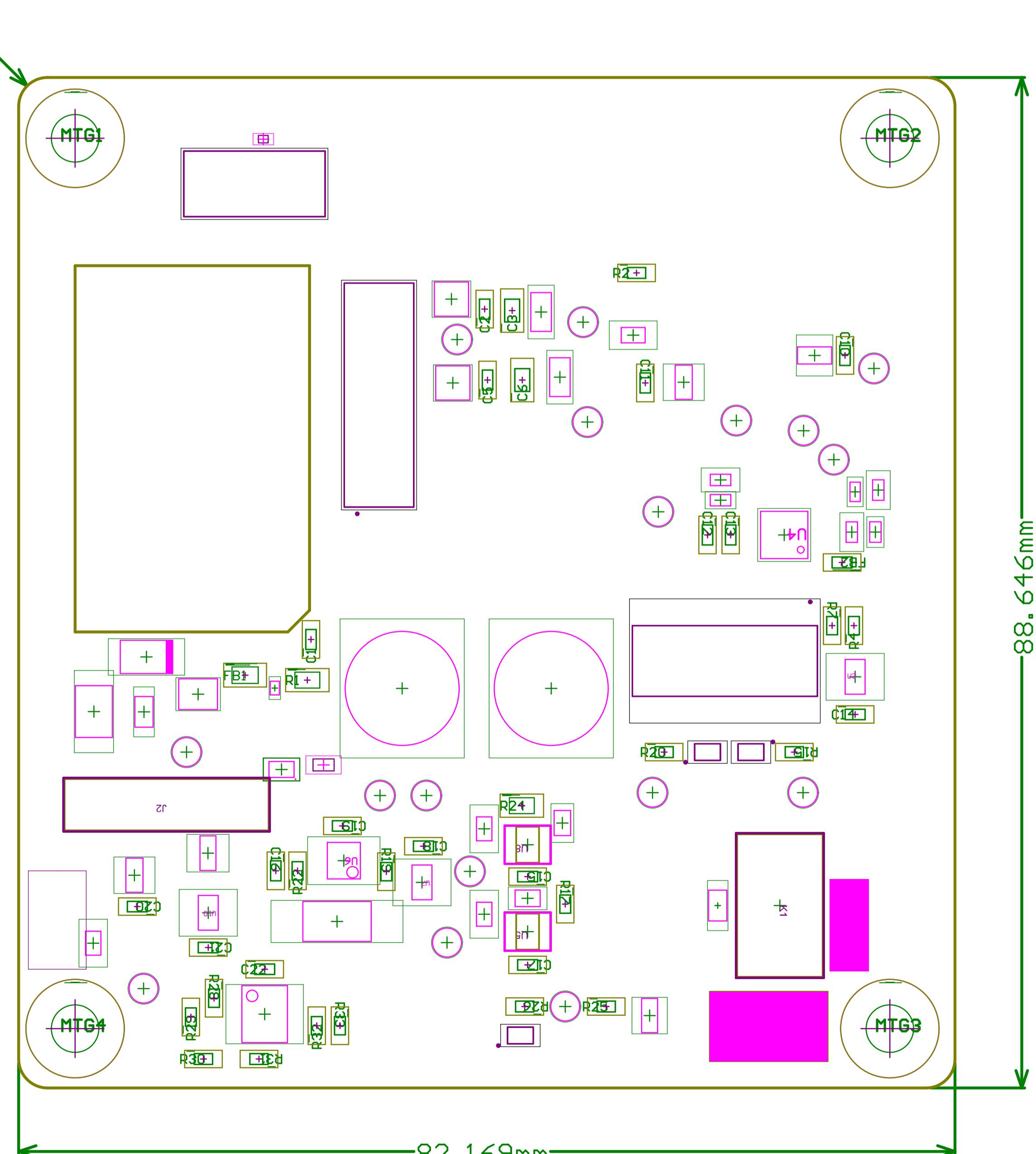
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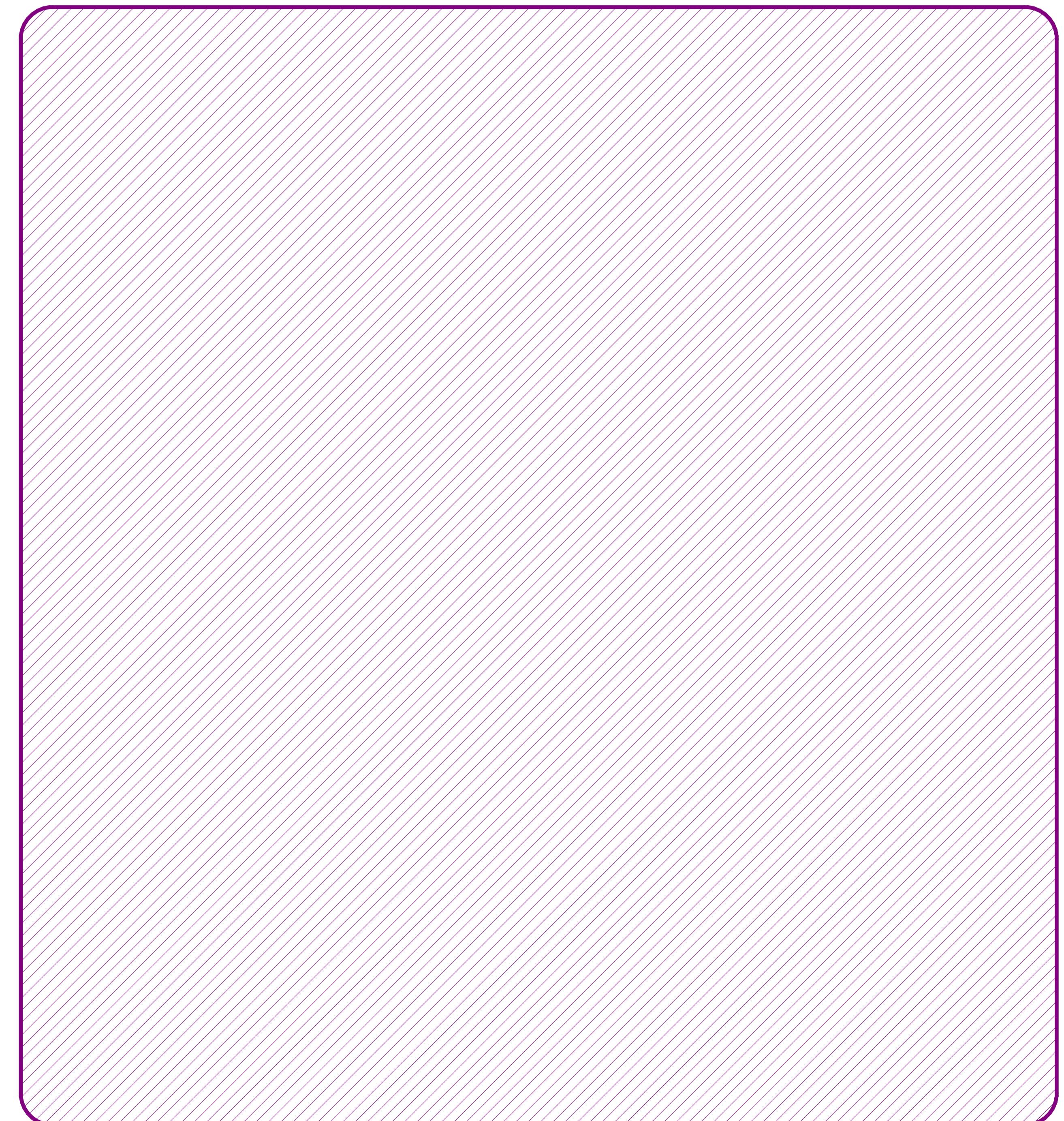
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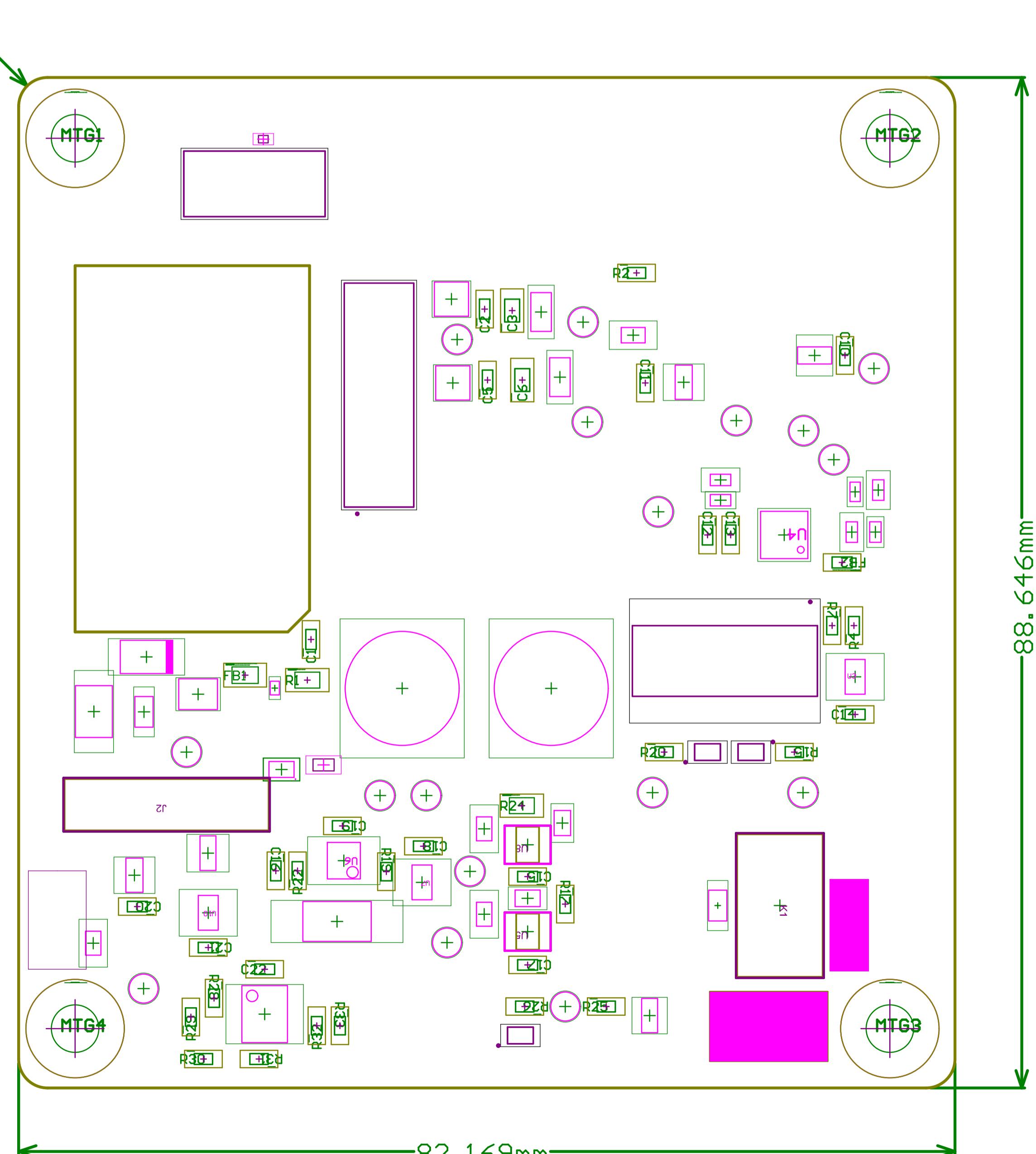
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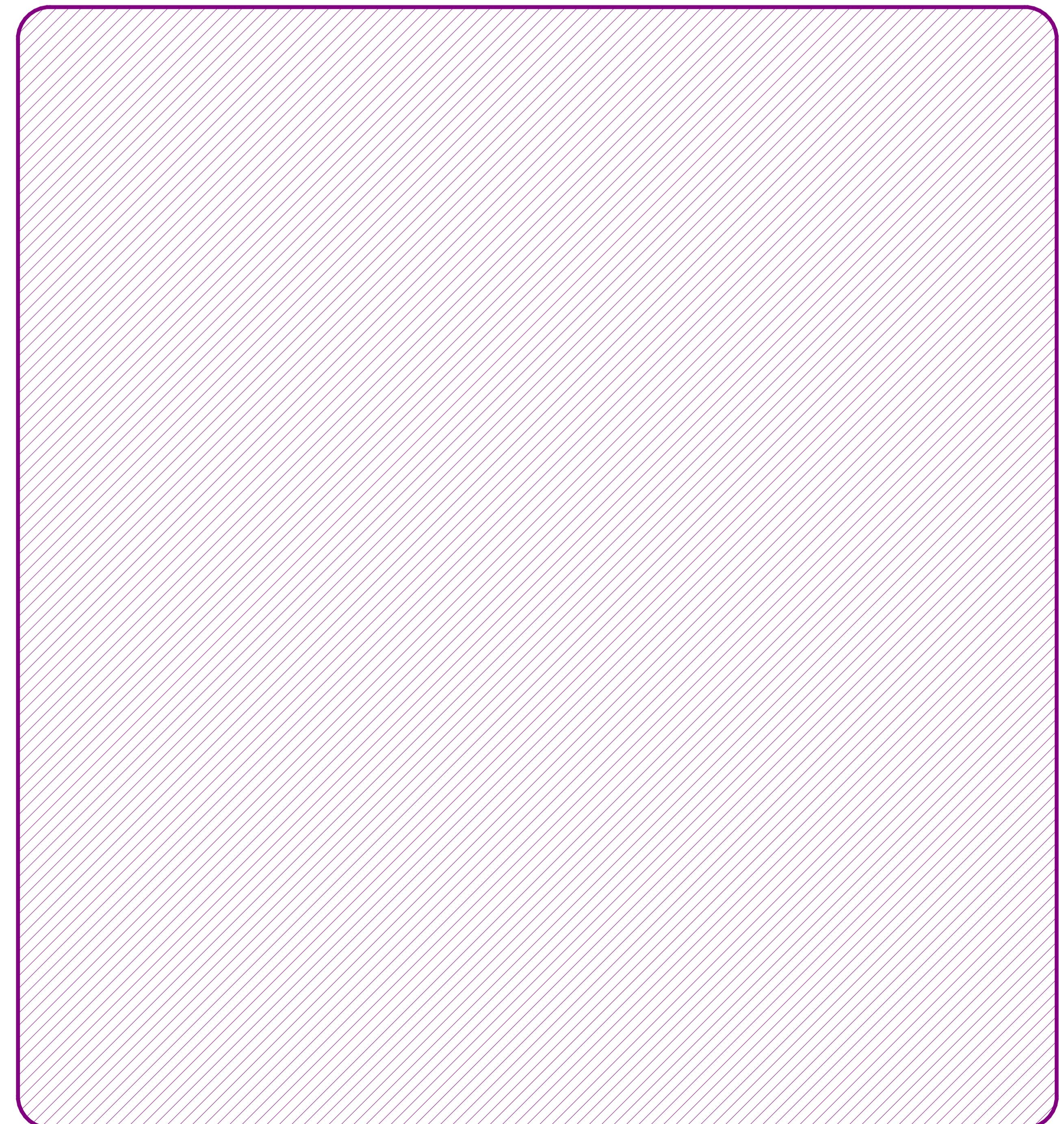
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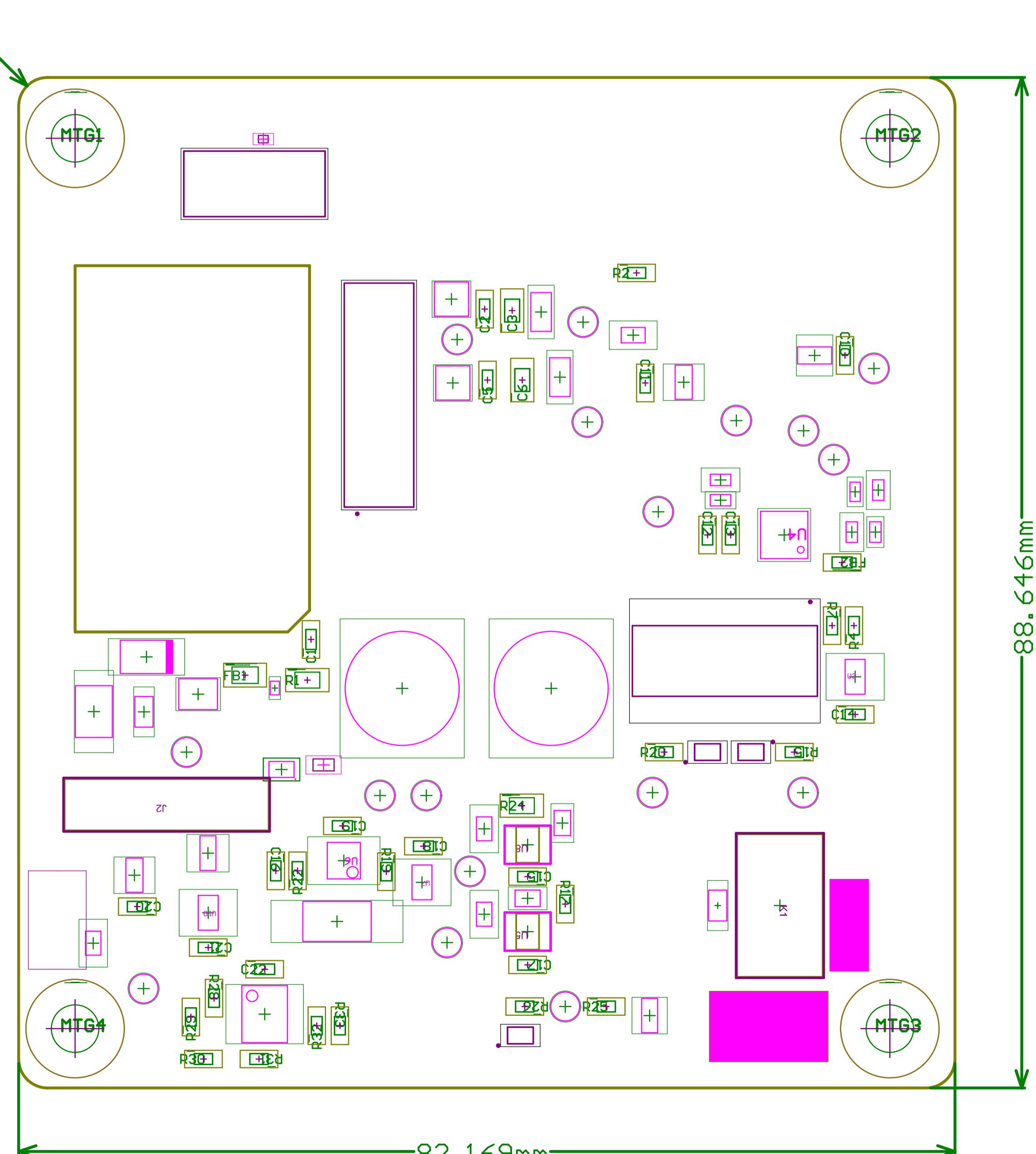
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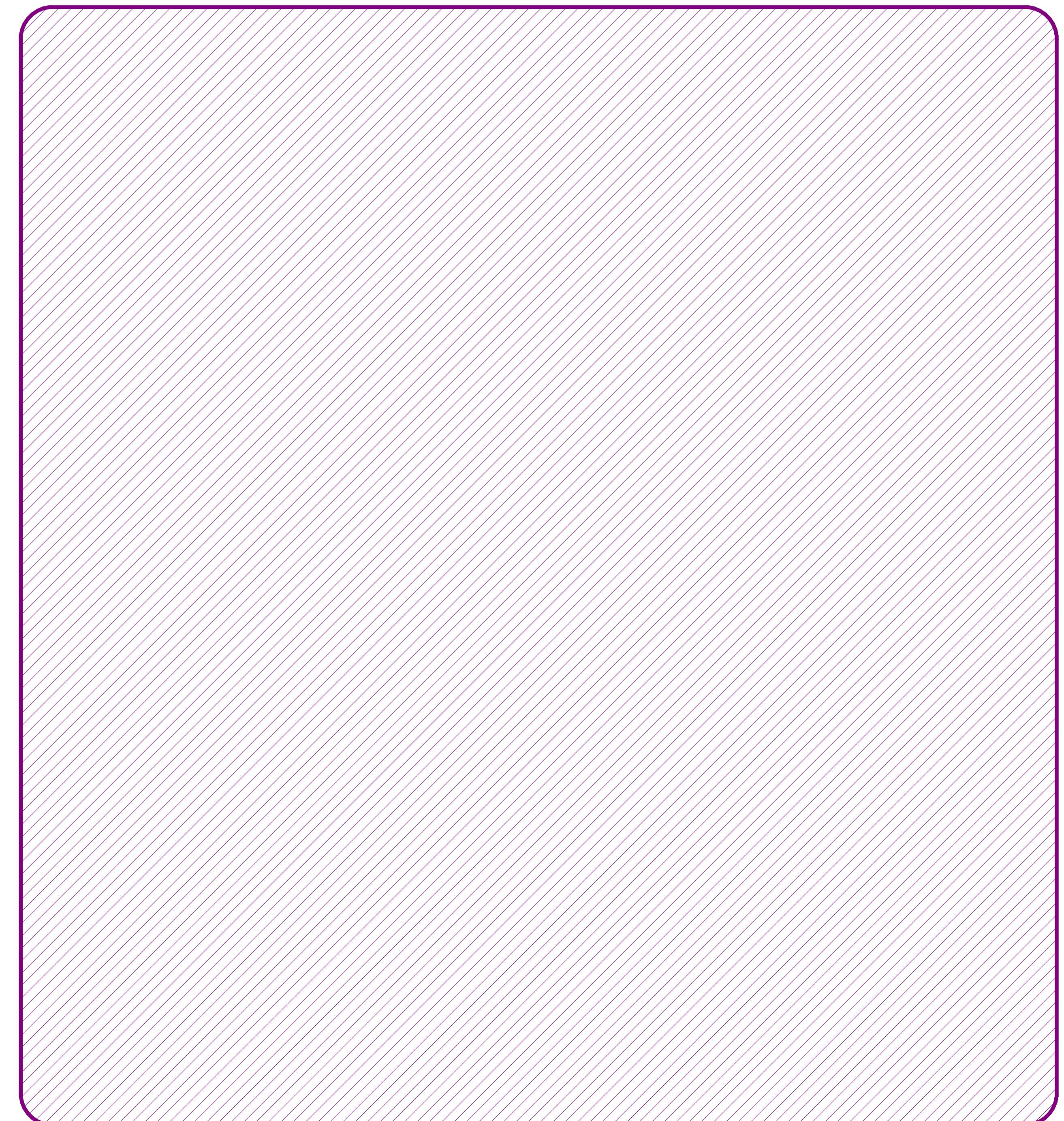
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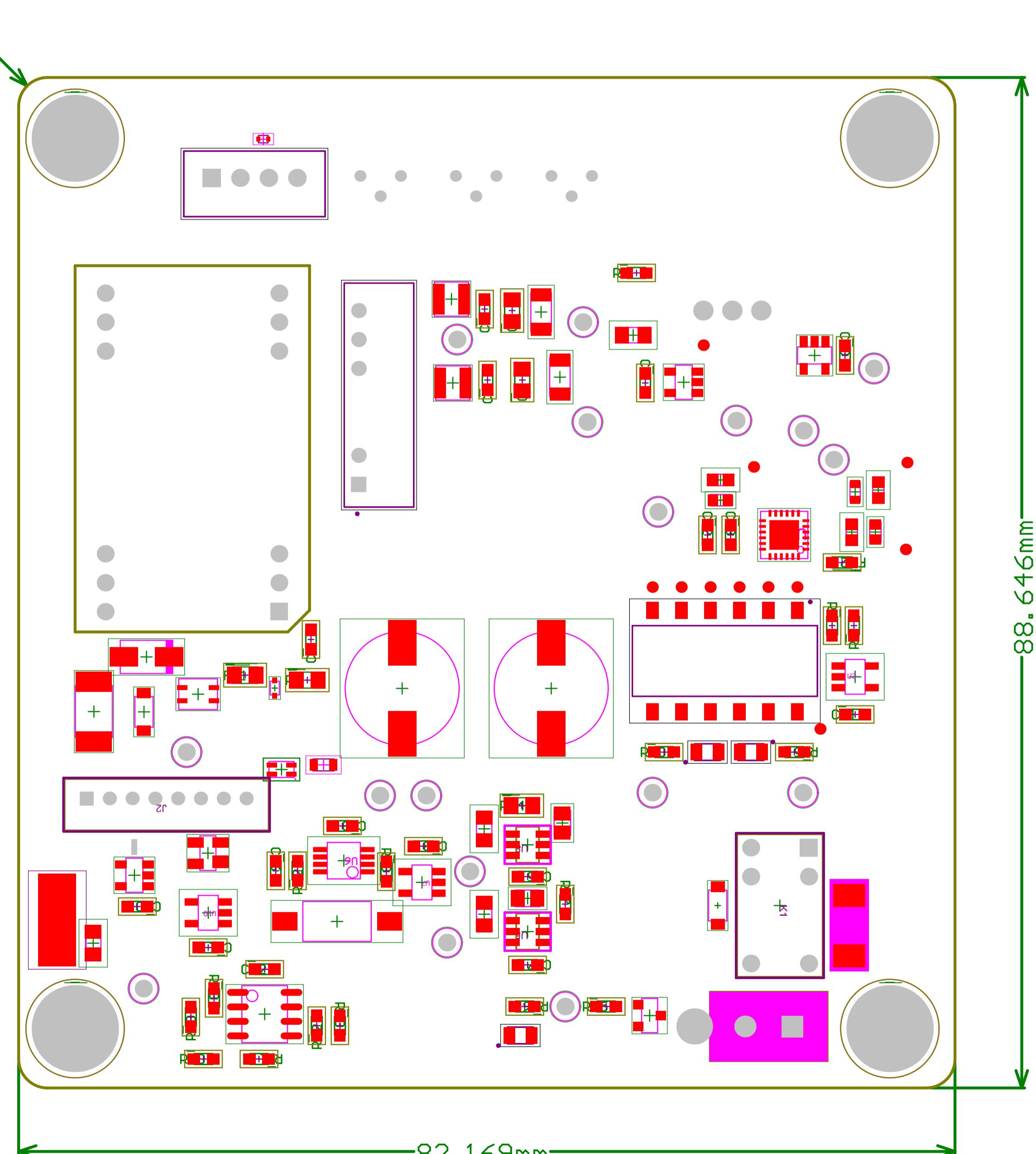
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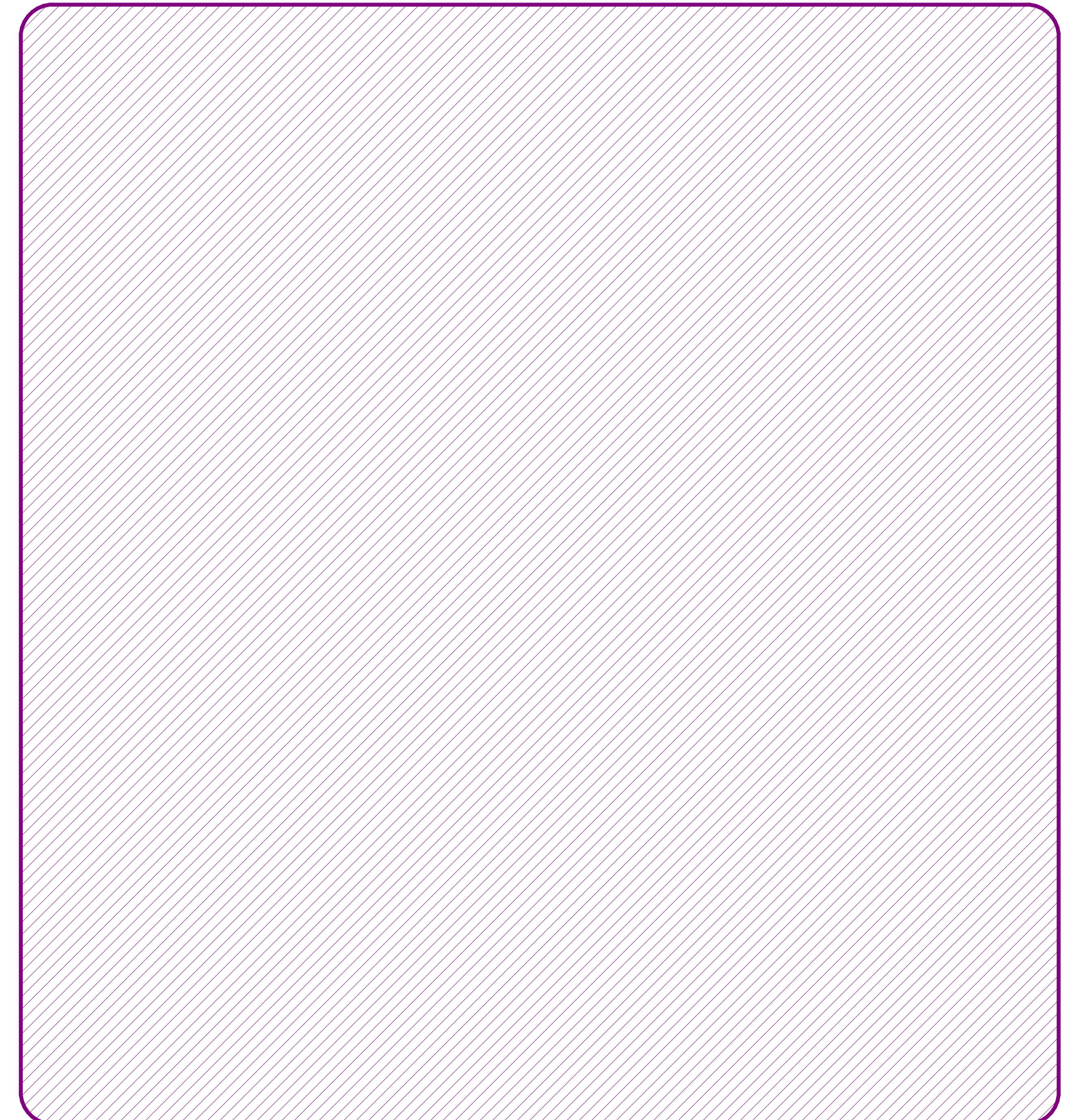
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Title <b>BSPD</b>			Designer: Andrew Katz aakatz@gmail.com
Size: Letter	Number:	Revision:	*
Date: 2/5/2020	Time: 2:26:28 PM	Sheet 1 of 1	*
File: UVM AERO BSPD.PcbDoc			

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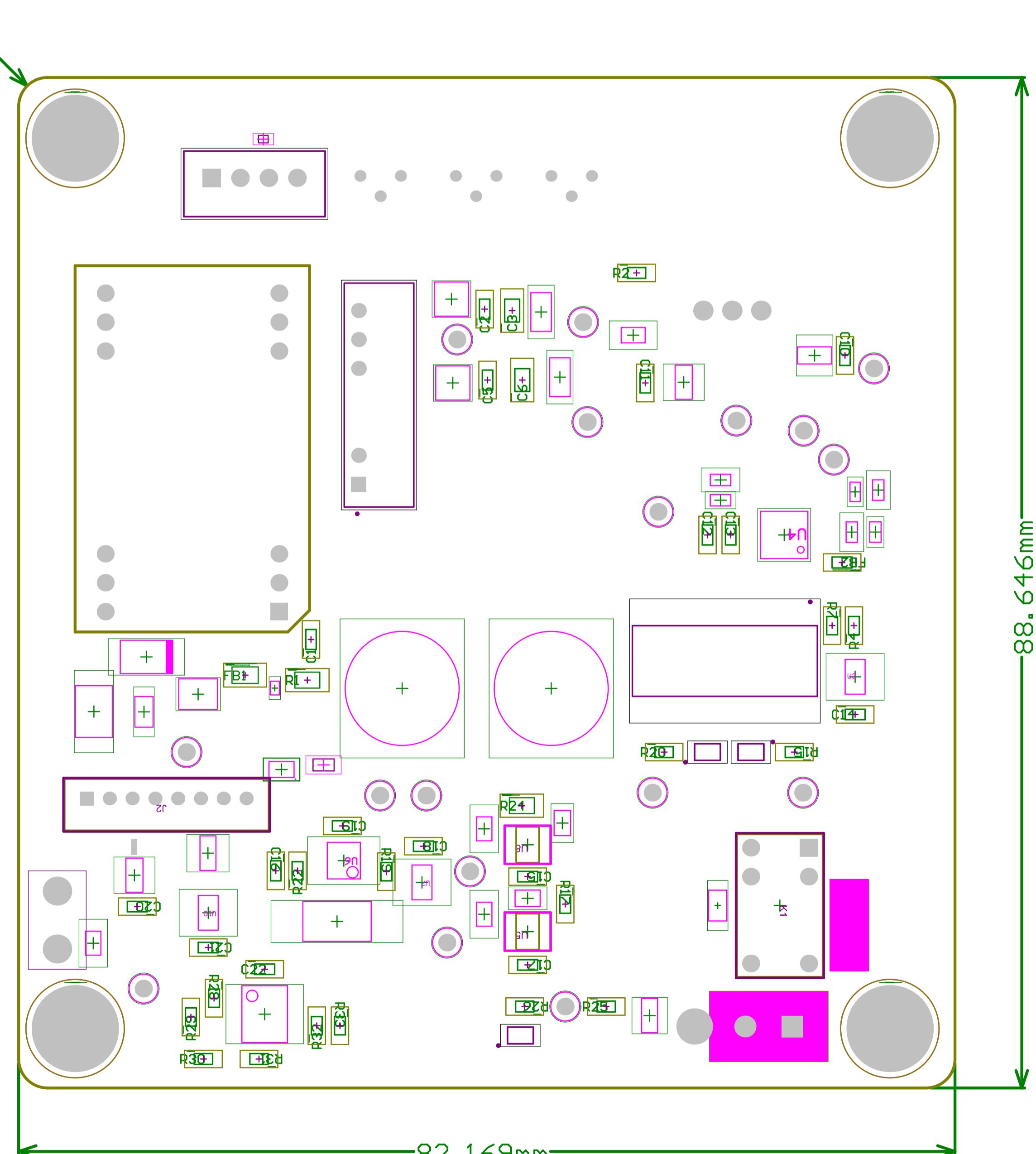
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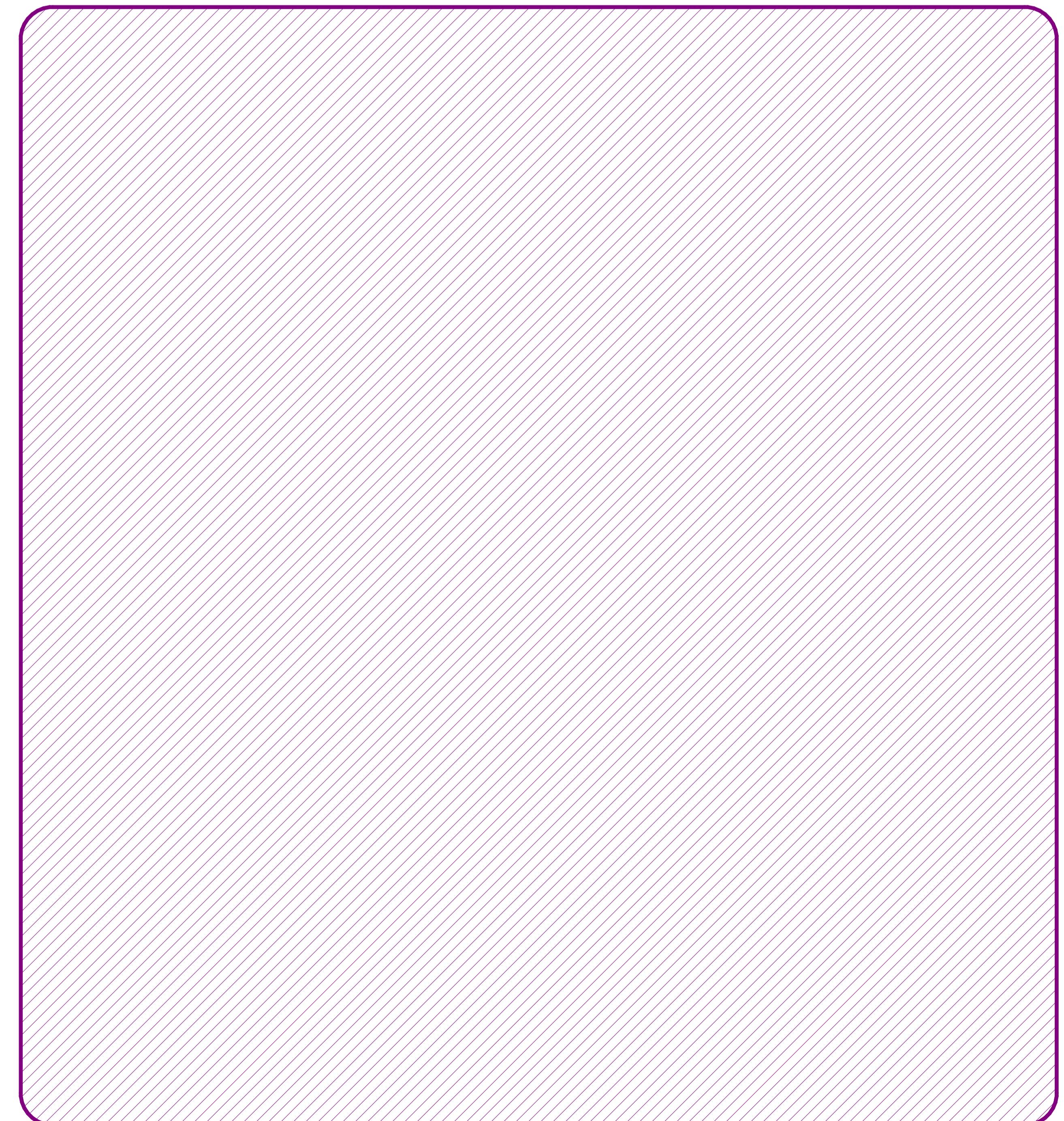
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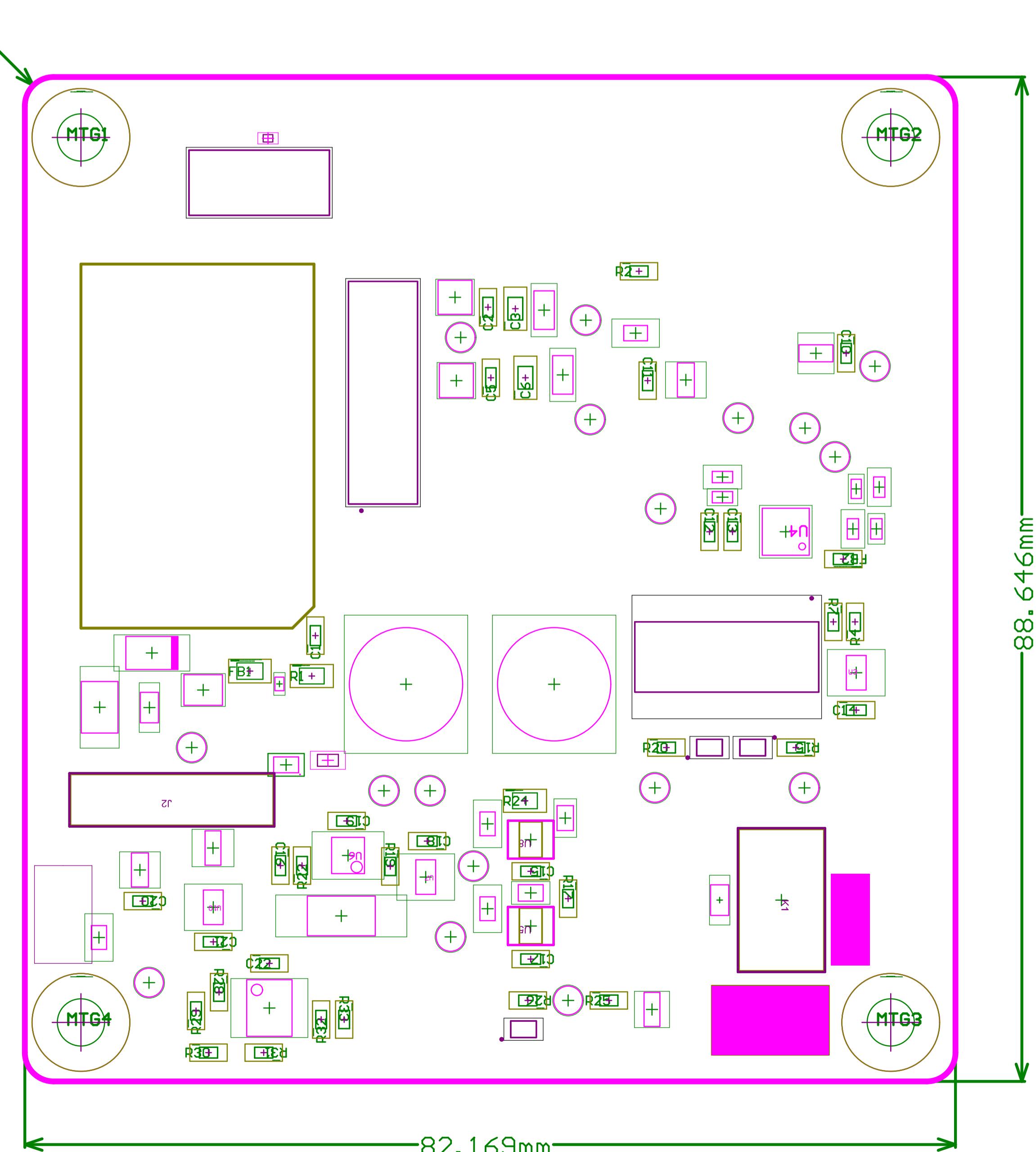
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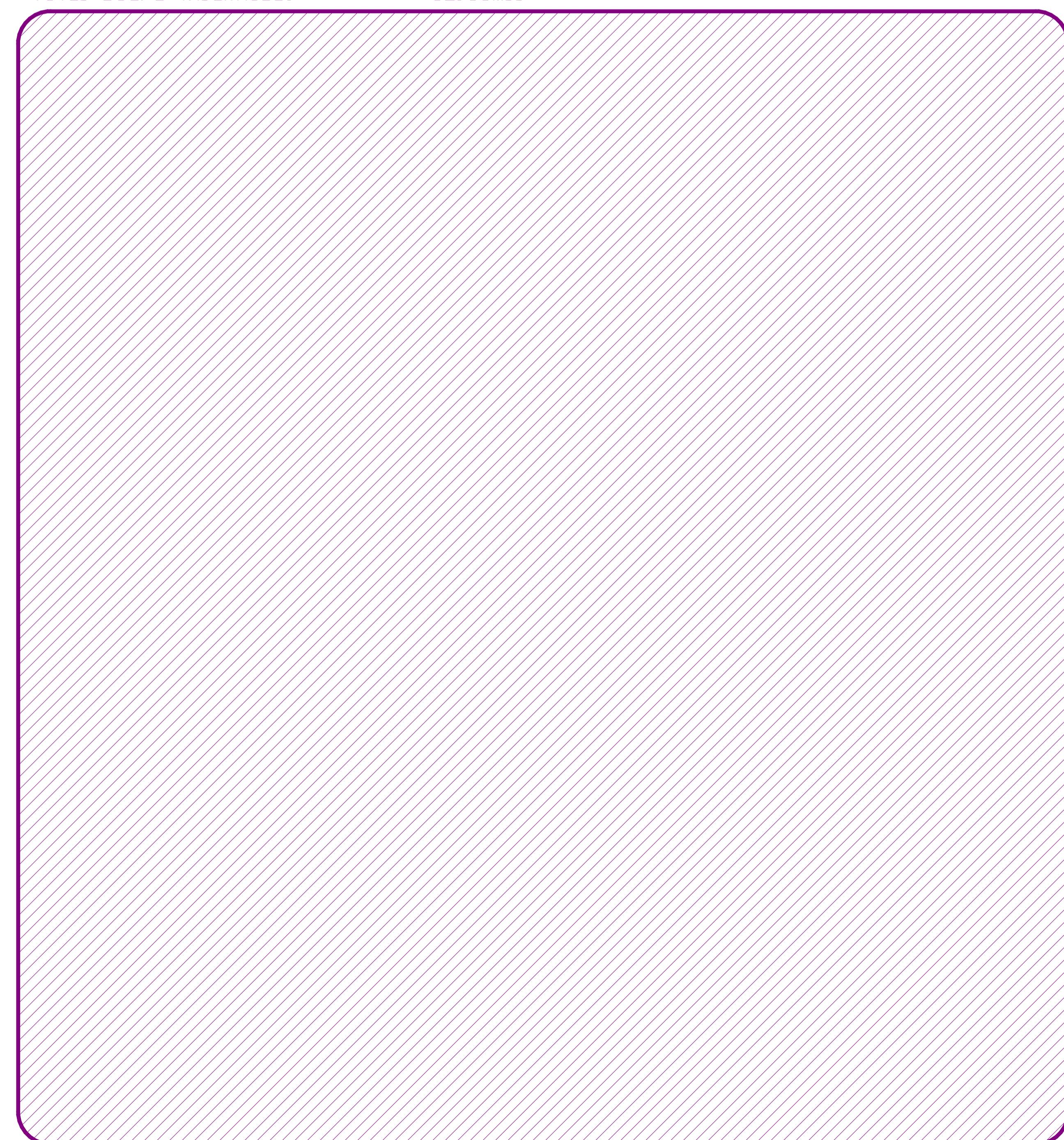
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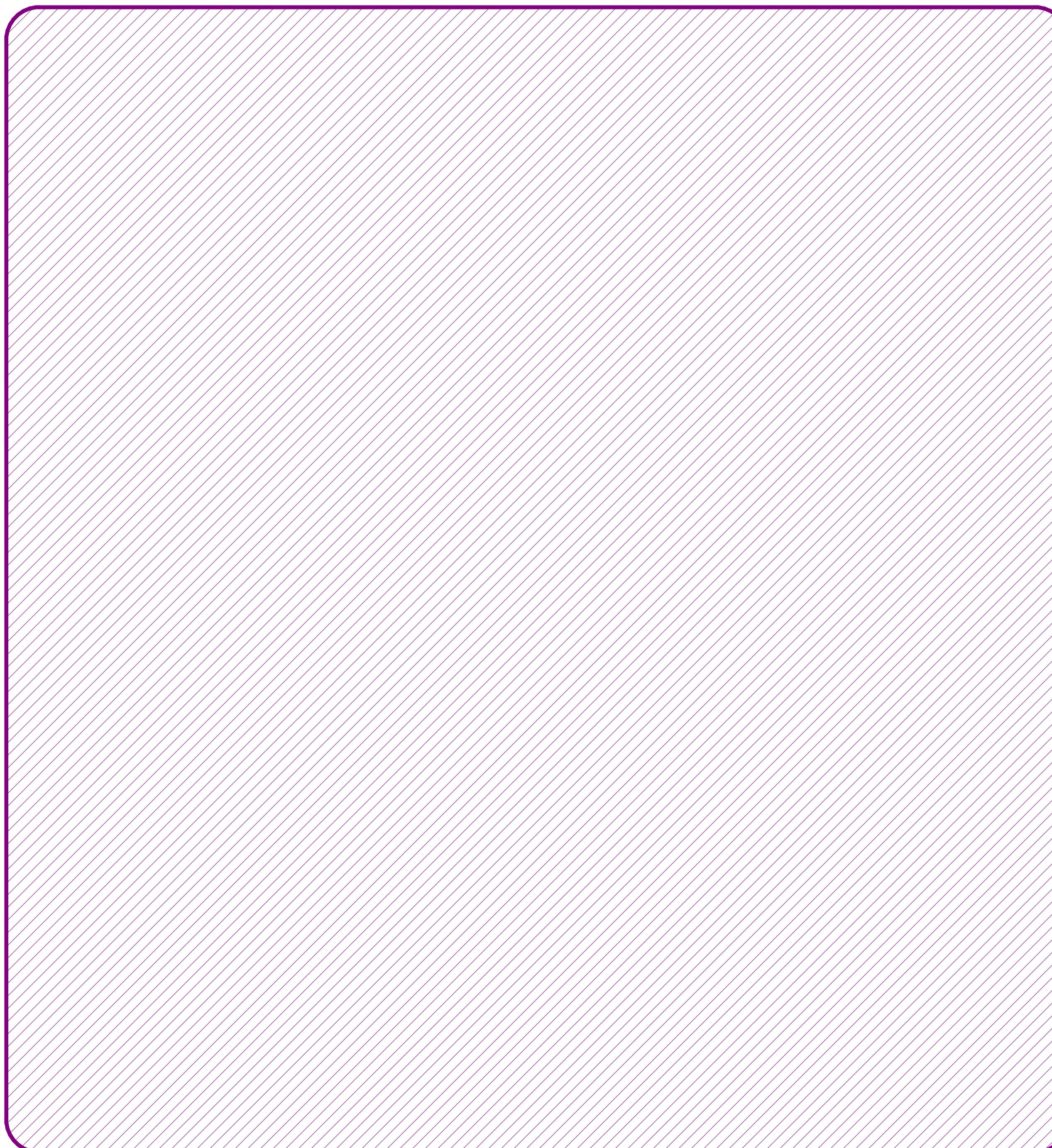
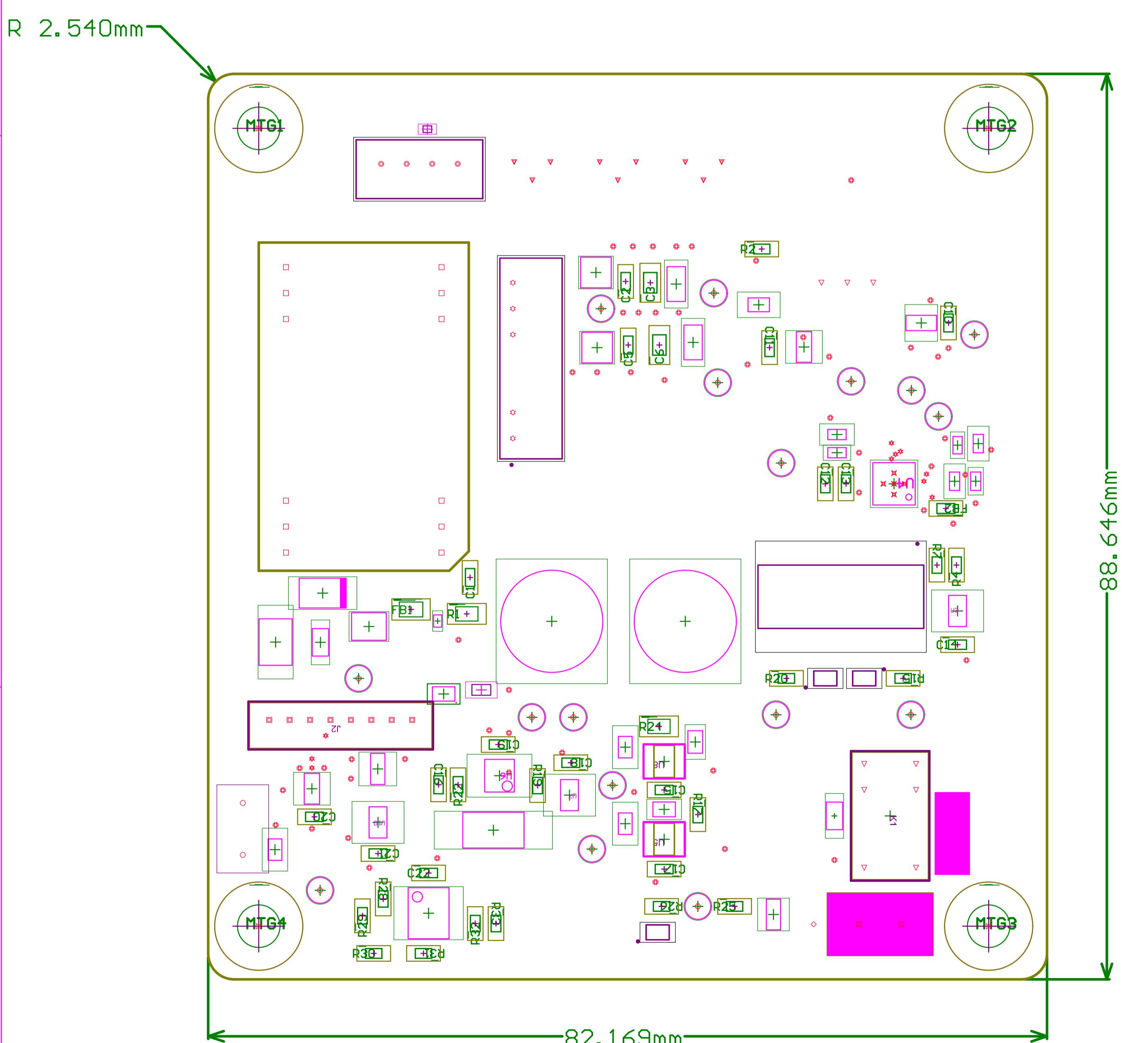
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Size: Letter	Number:	Revision:	*
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File: UVM AERO BSPD.PcbDoc			

**AERO**

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad	Pad Shape	Template
◊	1	125.00mil (3.175mm)	NPTH	Round	Pad	Rounded	c318hn318m0mx0
☒	2	55.00mil (1.397mm)	PTH	Round	Pad	(Mixed)	(Mixed)
○	2	57.00mil (1.448mm)	PTH	Round	Pad	Rounded	c254h145
◎	4	41.73mil (1.060mm)	PTH	Round	Pad	(Mixed)	(Mixed)
☒	4	142.00mil (3.607mm)	PTH	Round	Pad	Rounded	c762h361
☒	5	7.87mil (0.200mm)	PTH	Round	Via	Rounded	v50h20
☒	5	32.28mil (0.820mm)	PTH	Round	Pad	(Mixed)	(Mixed)
□	8	27.56mil (0.700mm)	PTH	Round	Pad	(Mixed)	(Mixed)
▽	9	20.00mil (0.508mm)	PTH	Round	Pad	Rounded	c102h51p25502
▽	9	39.37mil (1.000mm)	PTH	Round	Pad	(Mixed)	(Mixed)
★	10	9.00mil (0.229mm)	PTH	Round	(Mixed)	(Mixed)	(Mixed)
□	12	30.00mil (0.762mm)	PTH	Round	Pad	(Mixed)	(Mixed)
✚	17	40.00mil (1.016mm)	PTH	Round	Pad	Rounded	c155h102
☒	55	15.00mil (0.381mm)	PTH	Round	Via	Rounded	v76h38
<b>143 Total</b>							

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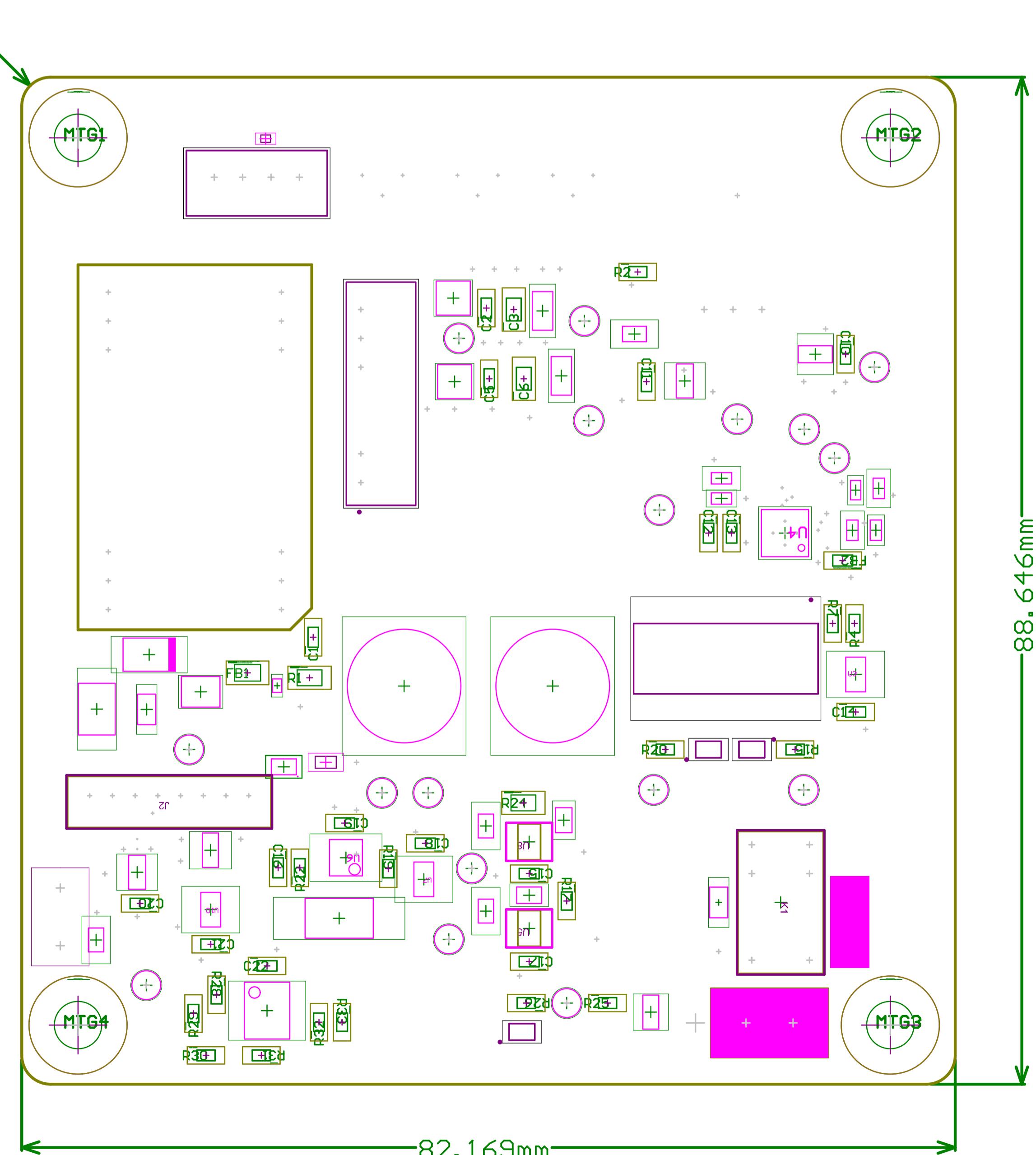
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